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**Kim et al.**

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(54) **SEMICONDUCTOR DEVICES AND METHODS OF MANUFACTURING THE SAME**

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**H01L 27/108** (2006.01)

**H01L 49/02** (2006.01)

(52) **U.S. Cl.**

CPC ..... **H01L 21/768** (2013.01); **H01L 27/10814** (2013.01); **H01L 27/10823** (2013.01); **H01L 27/10852** (2013.01); **H01L 27/10876** (2013.01); **H01L 27/10885** (2013.01); **H01L 28/91** (2013.01)

(58) **Field of Classification Search**

CPC ..... H01L 27/10814; H01L 27/10823; H01L 27/10852; H01L 27/10876; H01L 27/10885; H01L 28/91

See application file for complete search history.

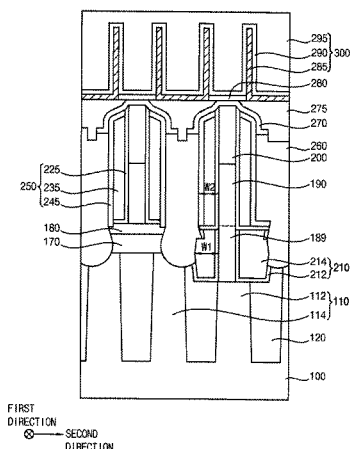
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**ABSTRACT**

A method of manufacturing a semiconductor device includes forming an isolation layer on a substrate, where an active pattern is defined, forming an insulating interlayer on the active pattern of the substrate and the isolation layer, removing portions of the insulating interlayer, the active pattern and the isolation layer to form a first recess, forming a first contact in the first recess on a first region of the active pattern exposed by the first recess, removing portions of the active pattern and the isolation layer in the first recess by performing an isotropic etching process, to form an enlarged first recess, and

filling the enlarged first recess to form a first spacer that surrounds a sidewall of the first contact.

**16 Claims, 26 Drawing Sheets**



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FIG. 1

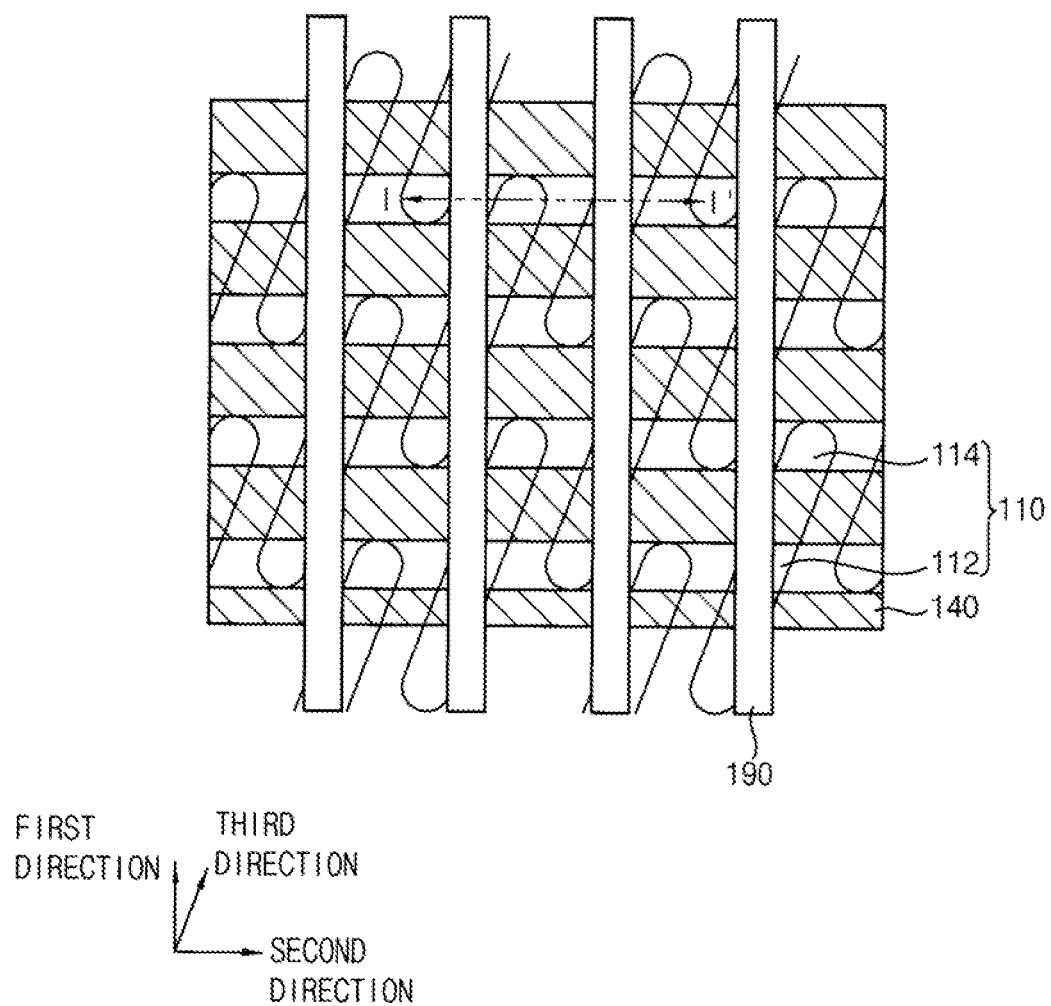
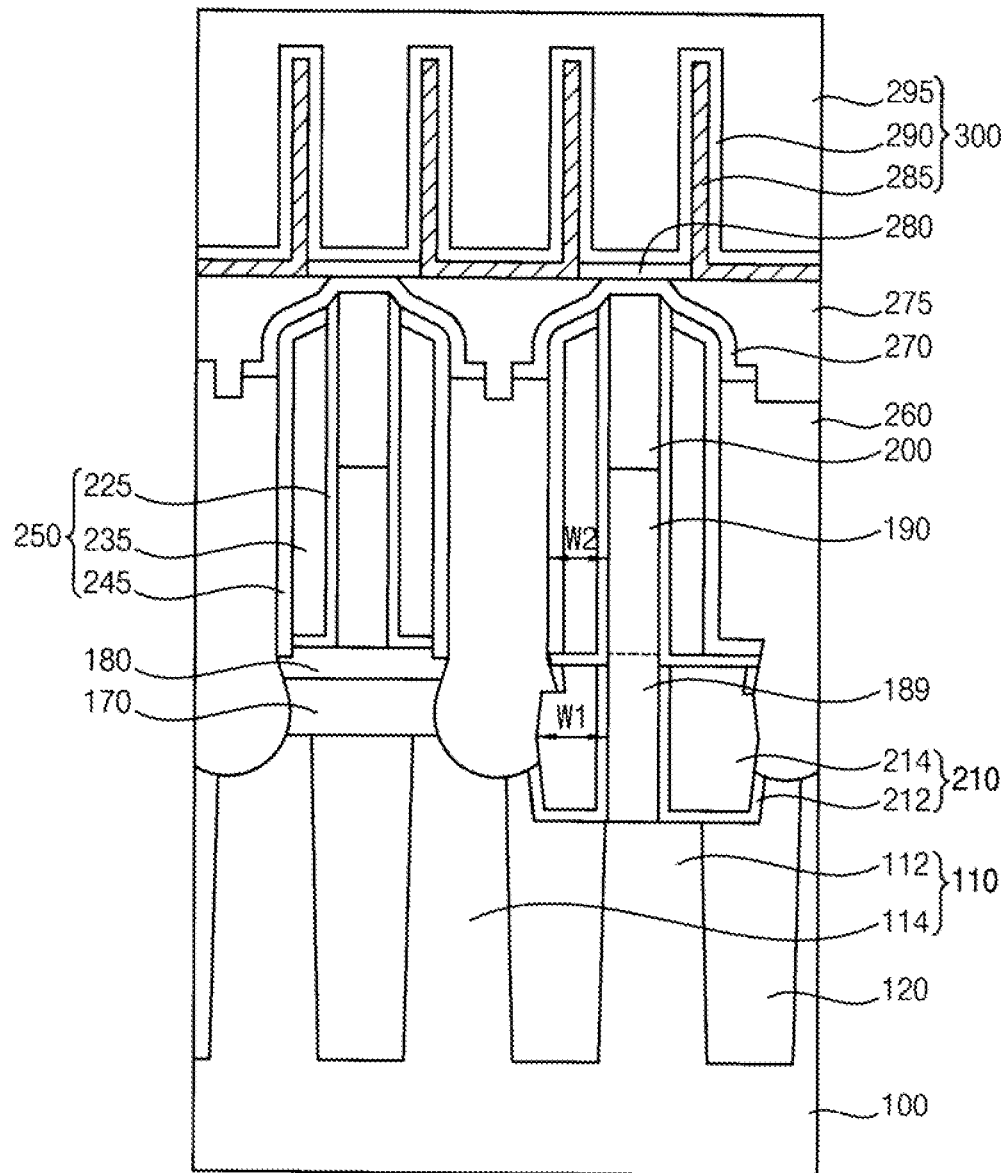


FIG. 2



FIRST  
DIRECTION  
⊗ → SECOND  
DIRECTION

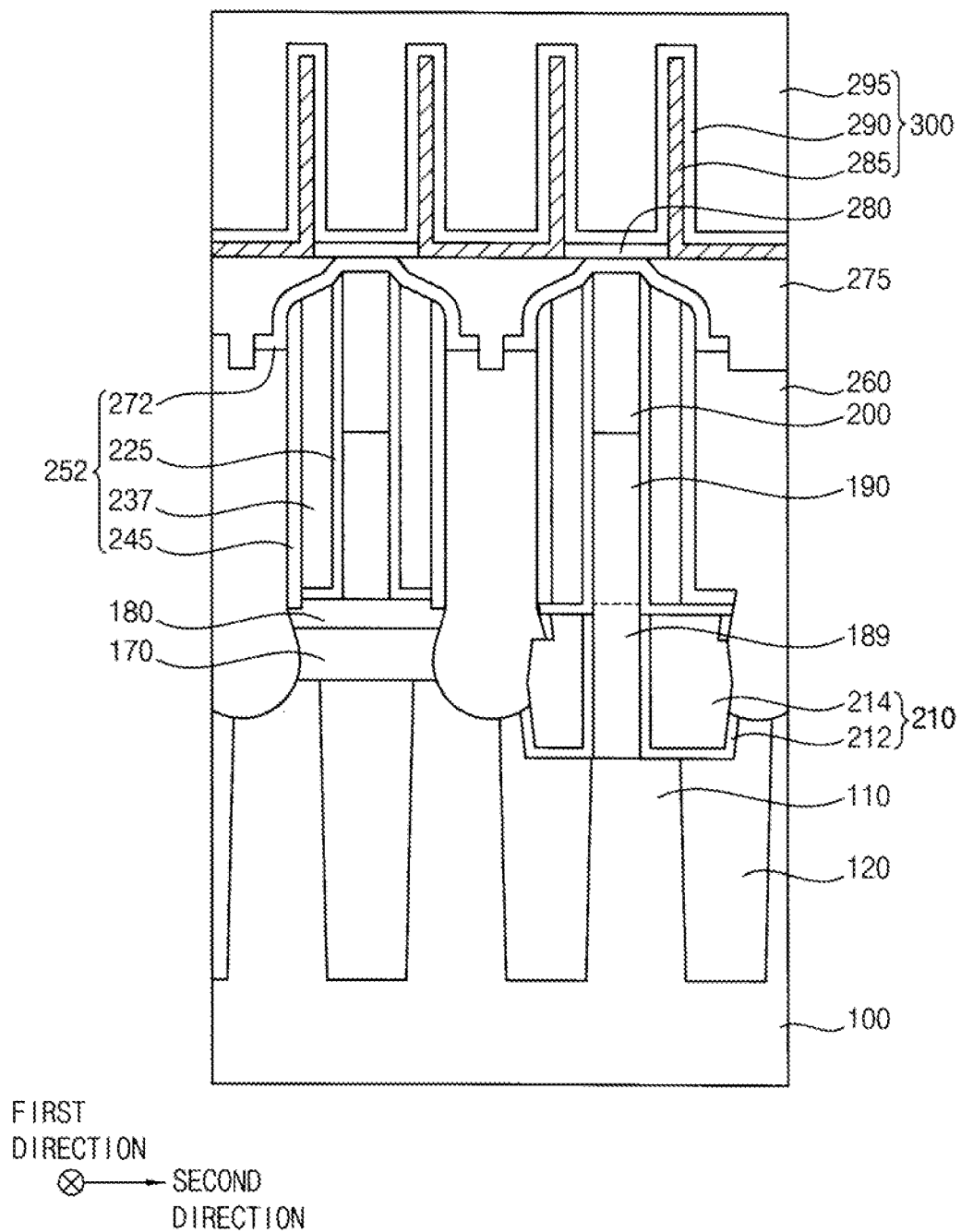


FIG. 4

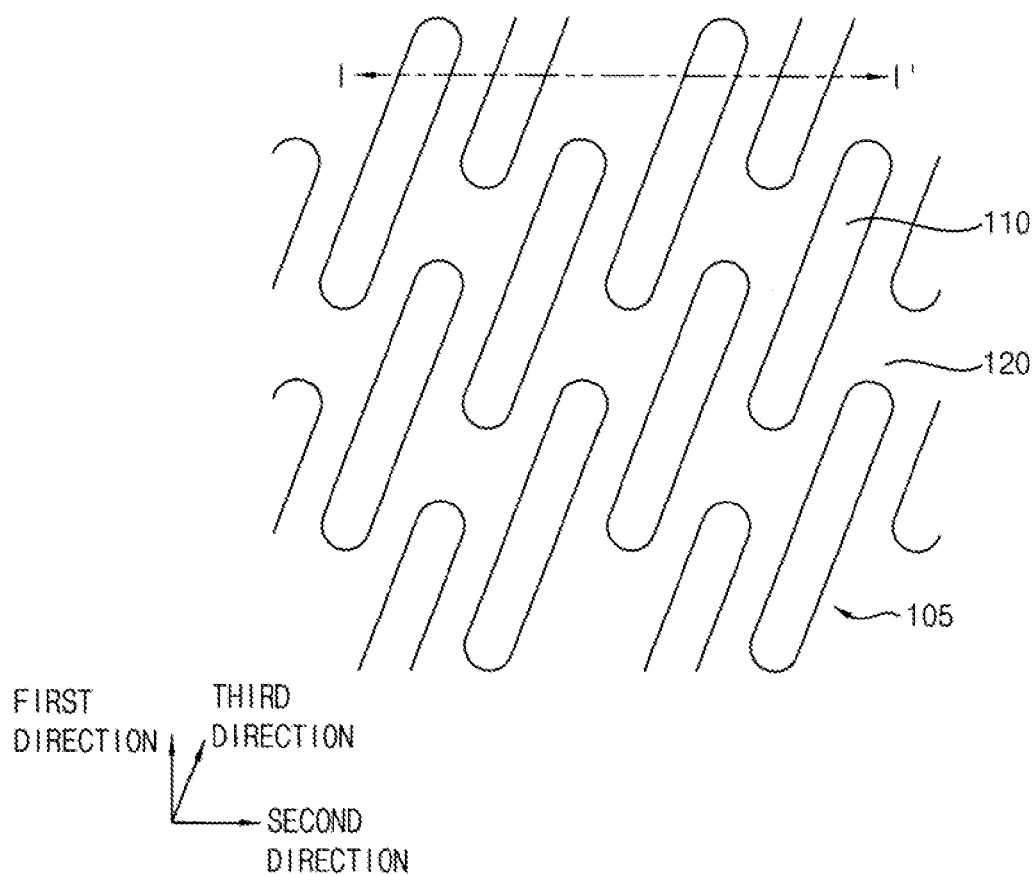


FIG. 5

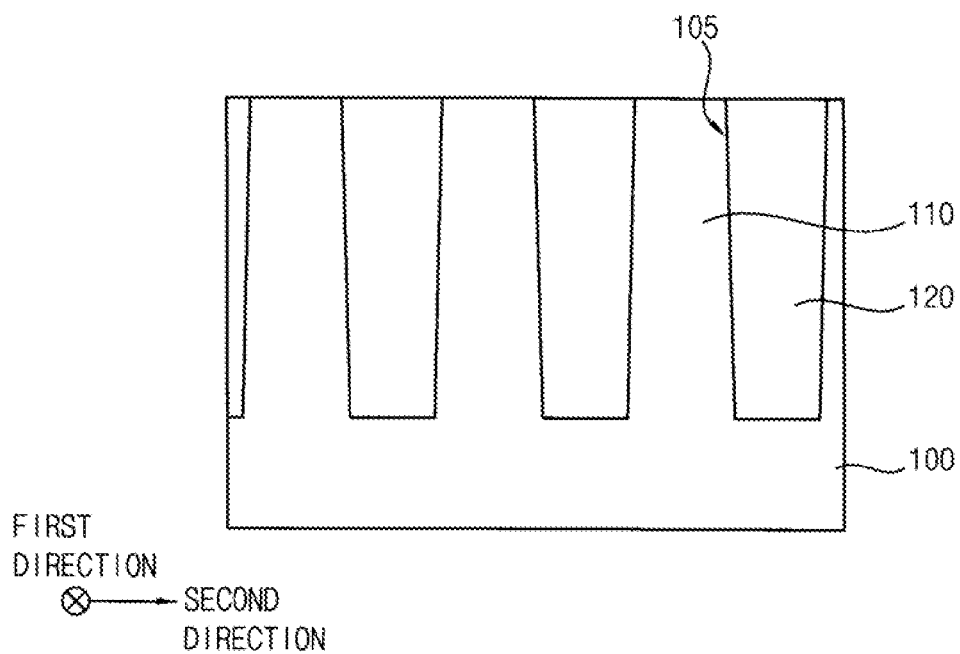


FIG. 6

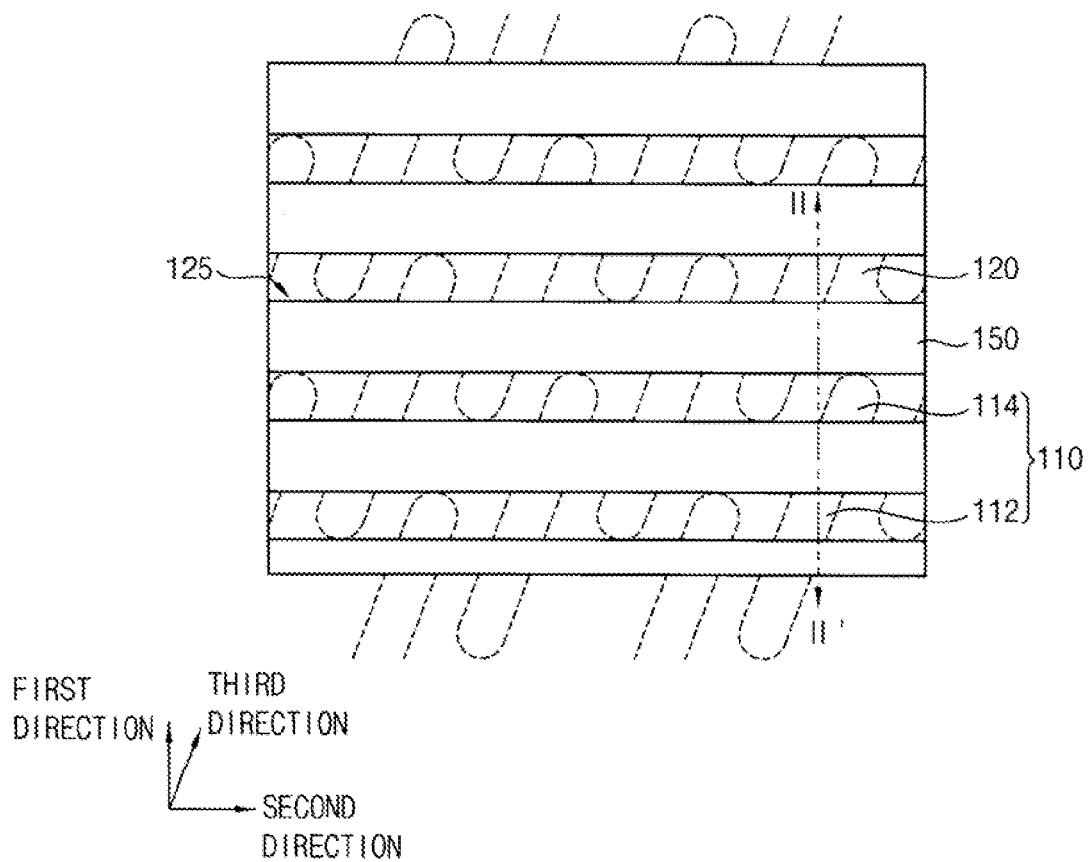


FIG. 7

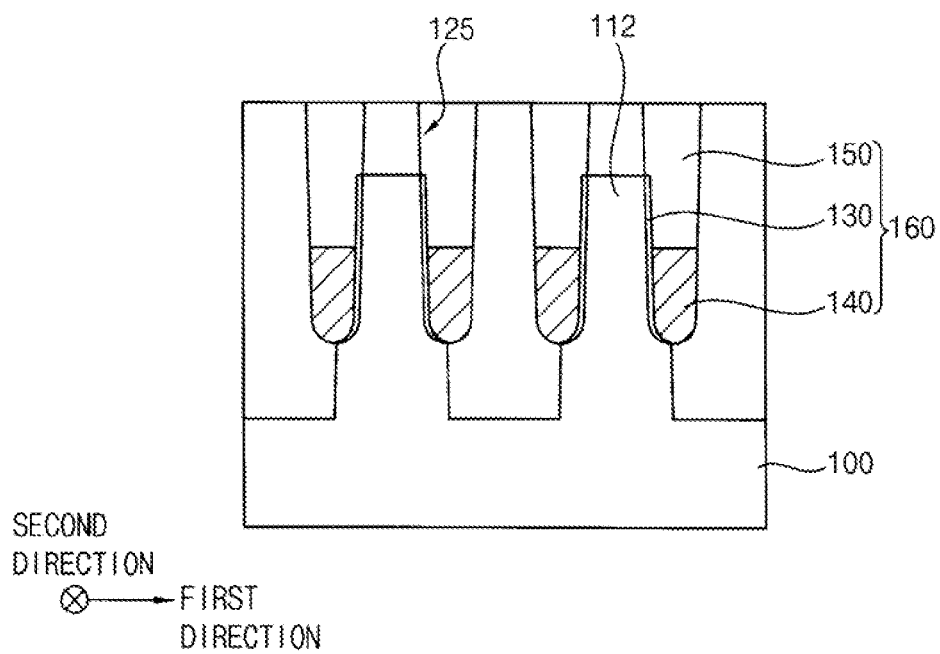


FIG. 8A

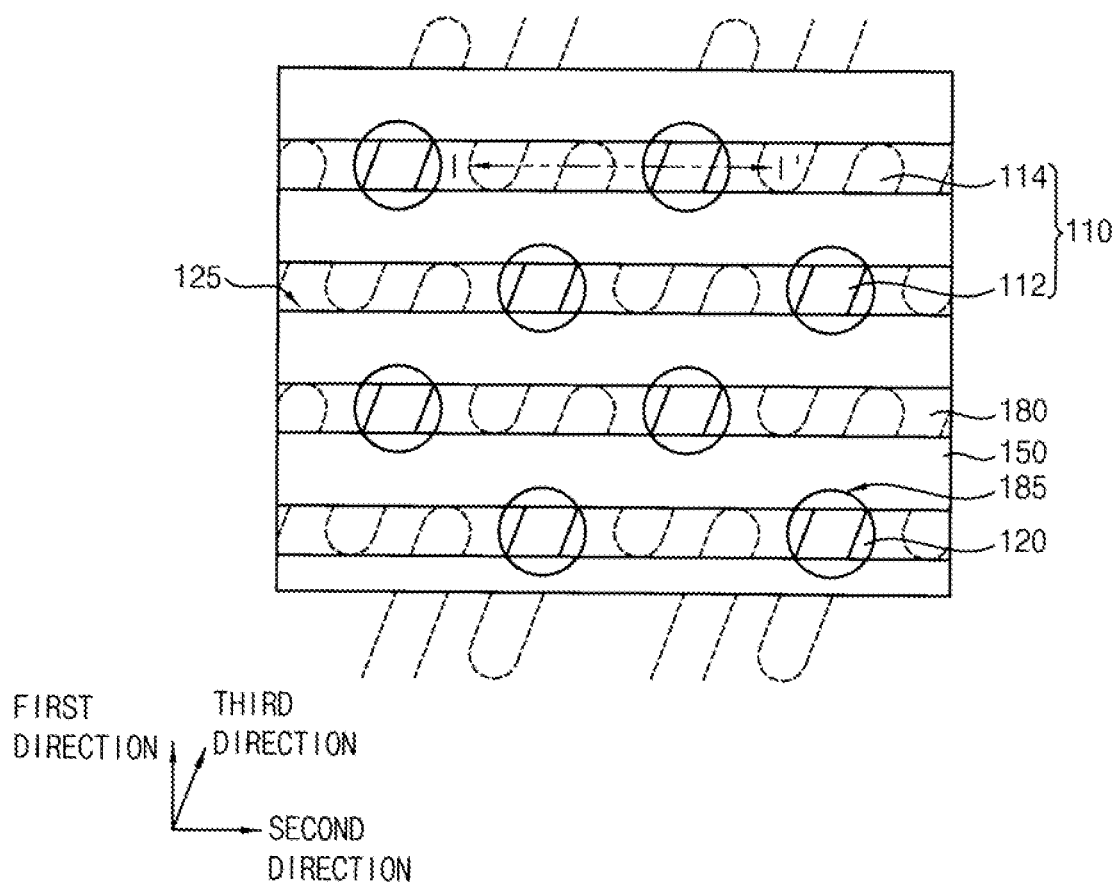




FIG. 8B

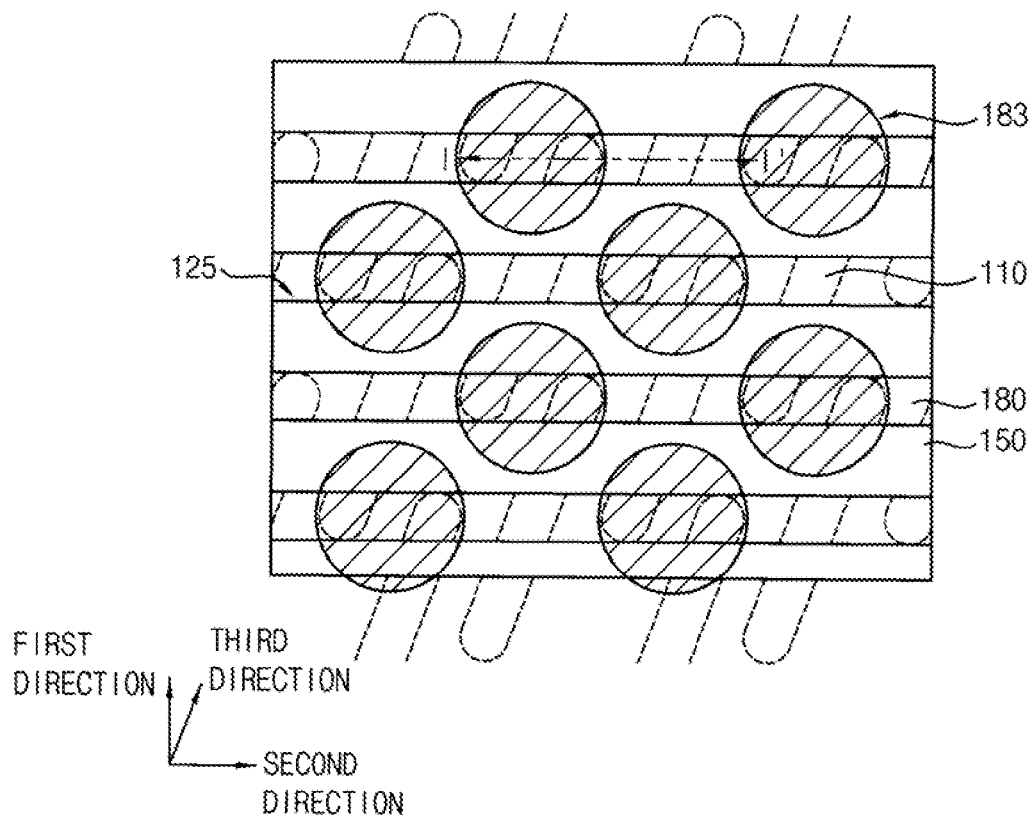


FIG. 9

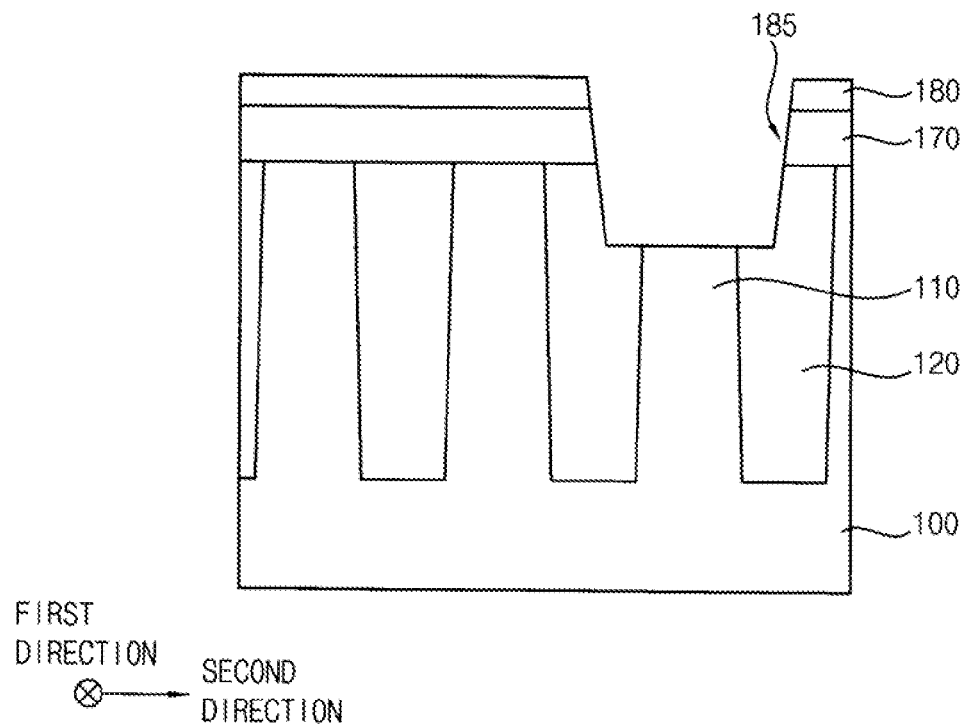


FIG. 10

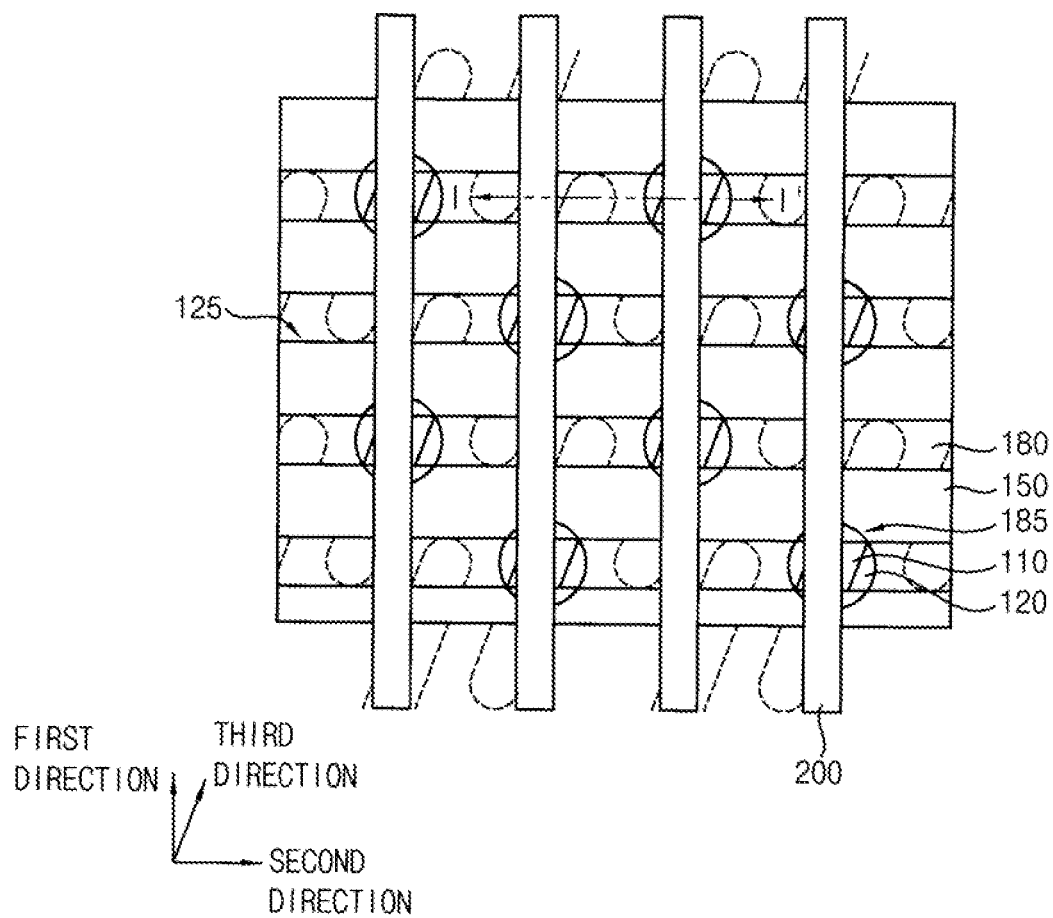


FIG. 11

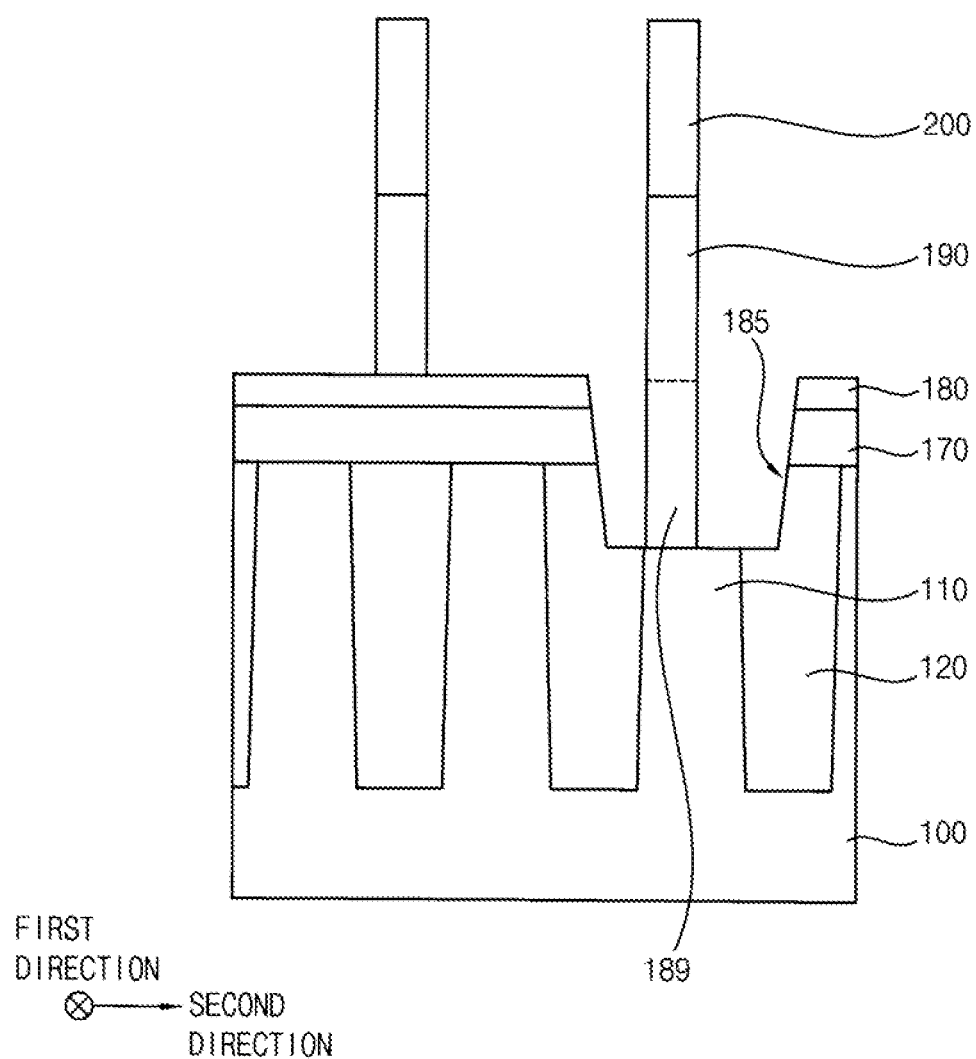


FIG. 12

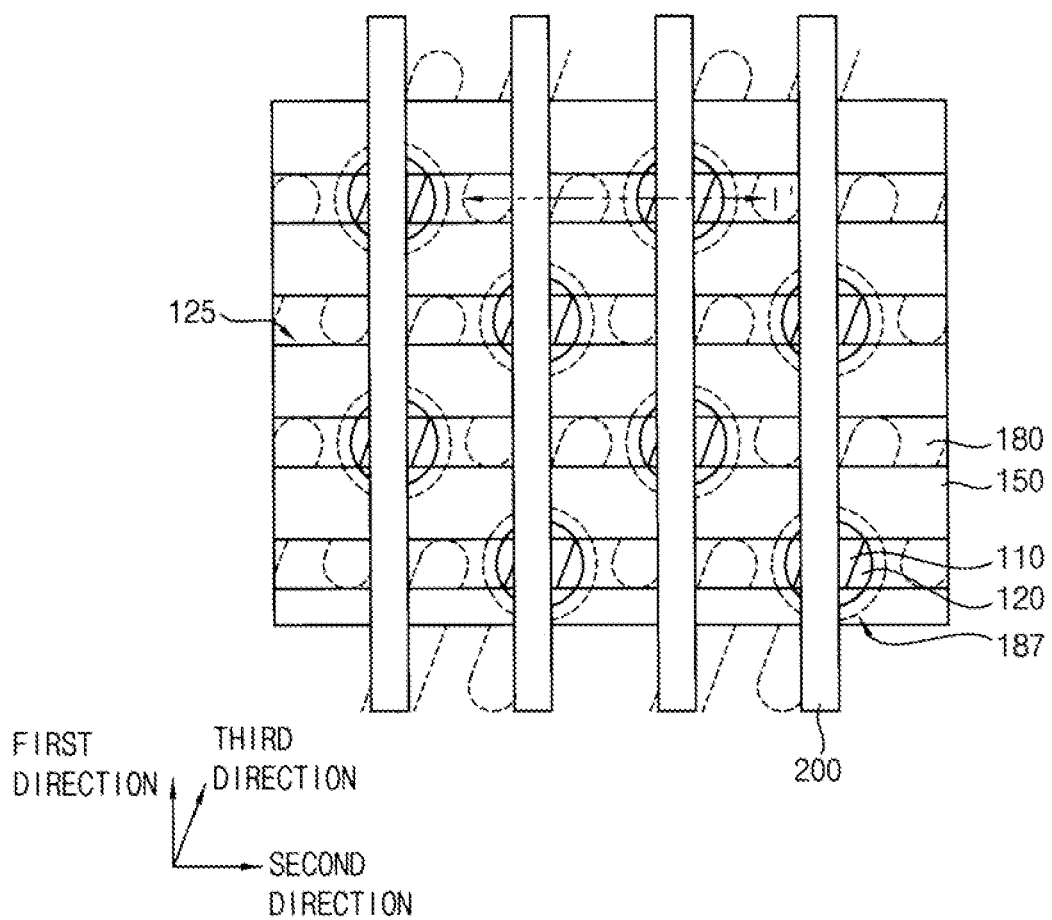


FIG. 13

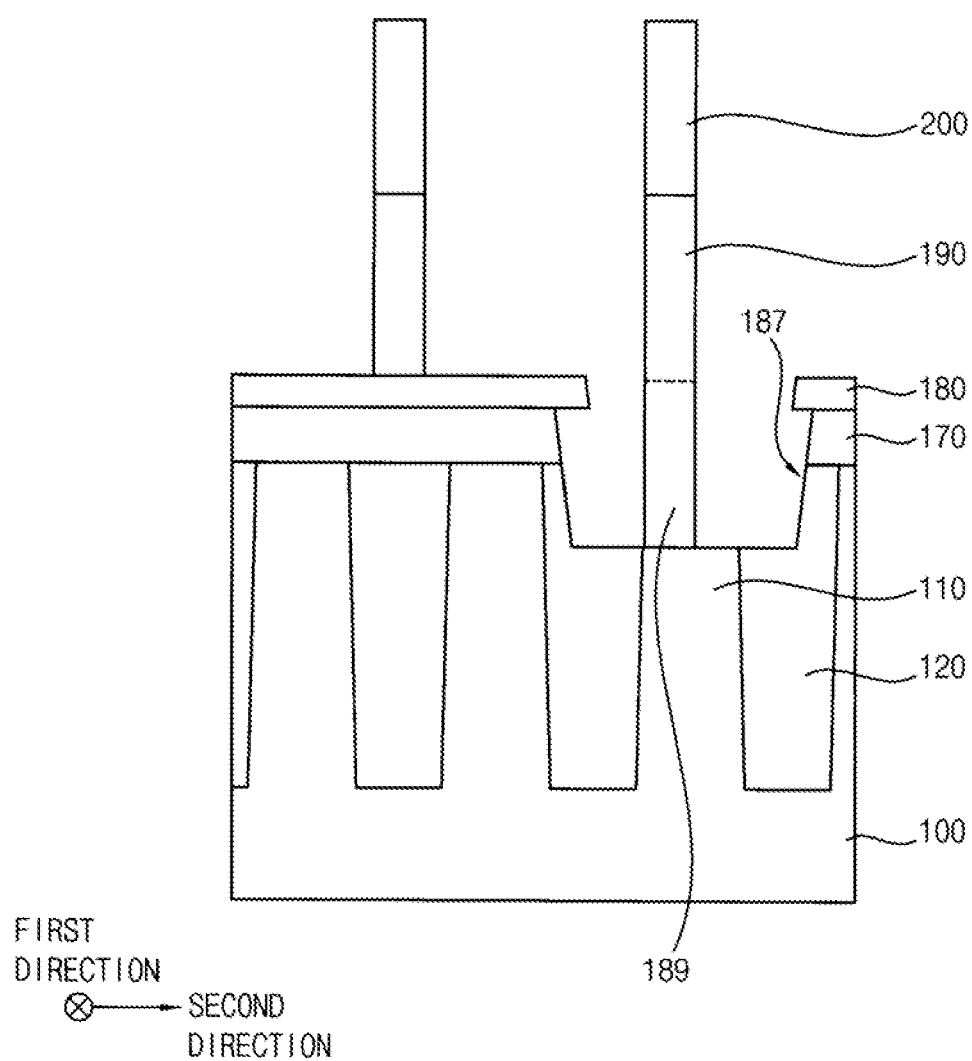


FIG. 14

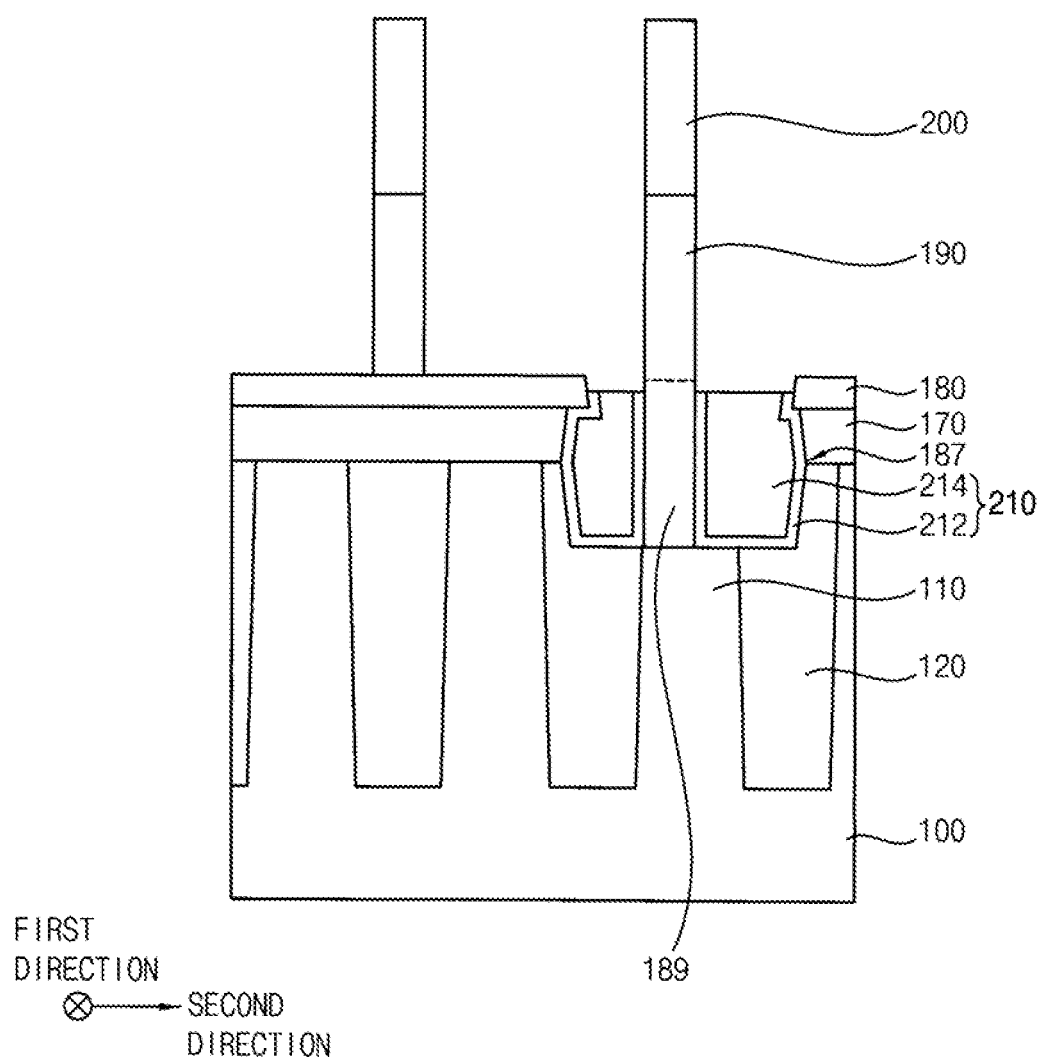


FIG. 15

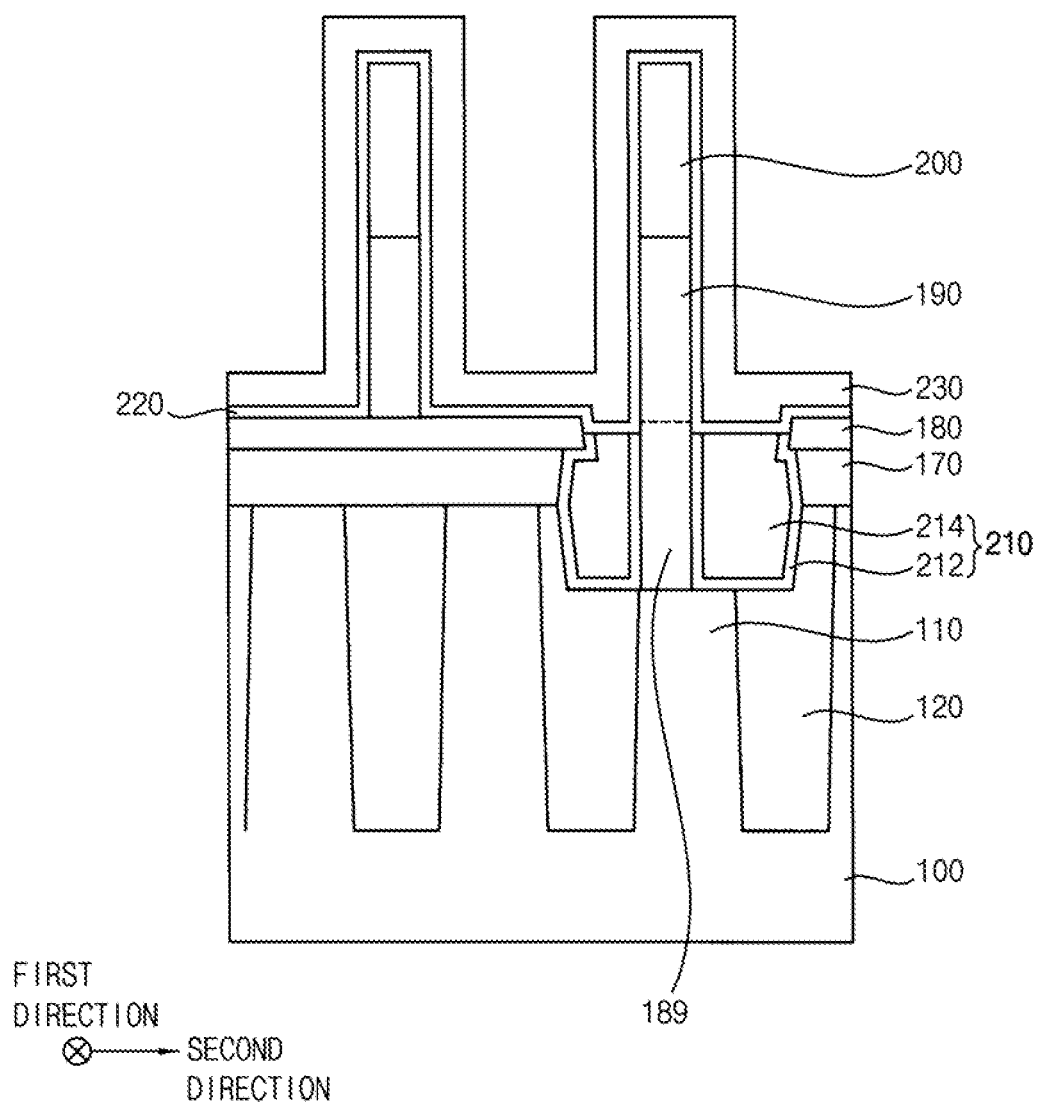


FIG. 16

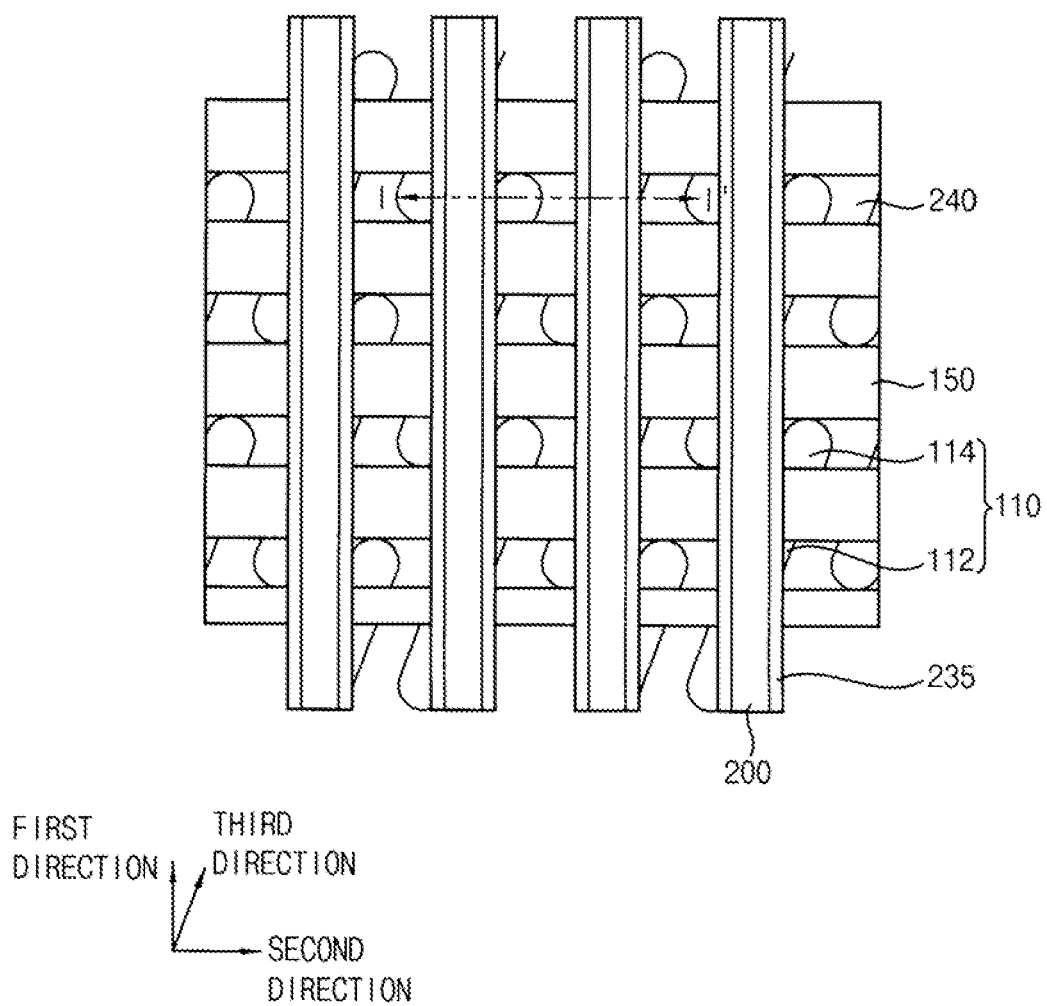




FIG. 17

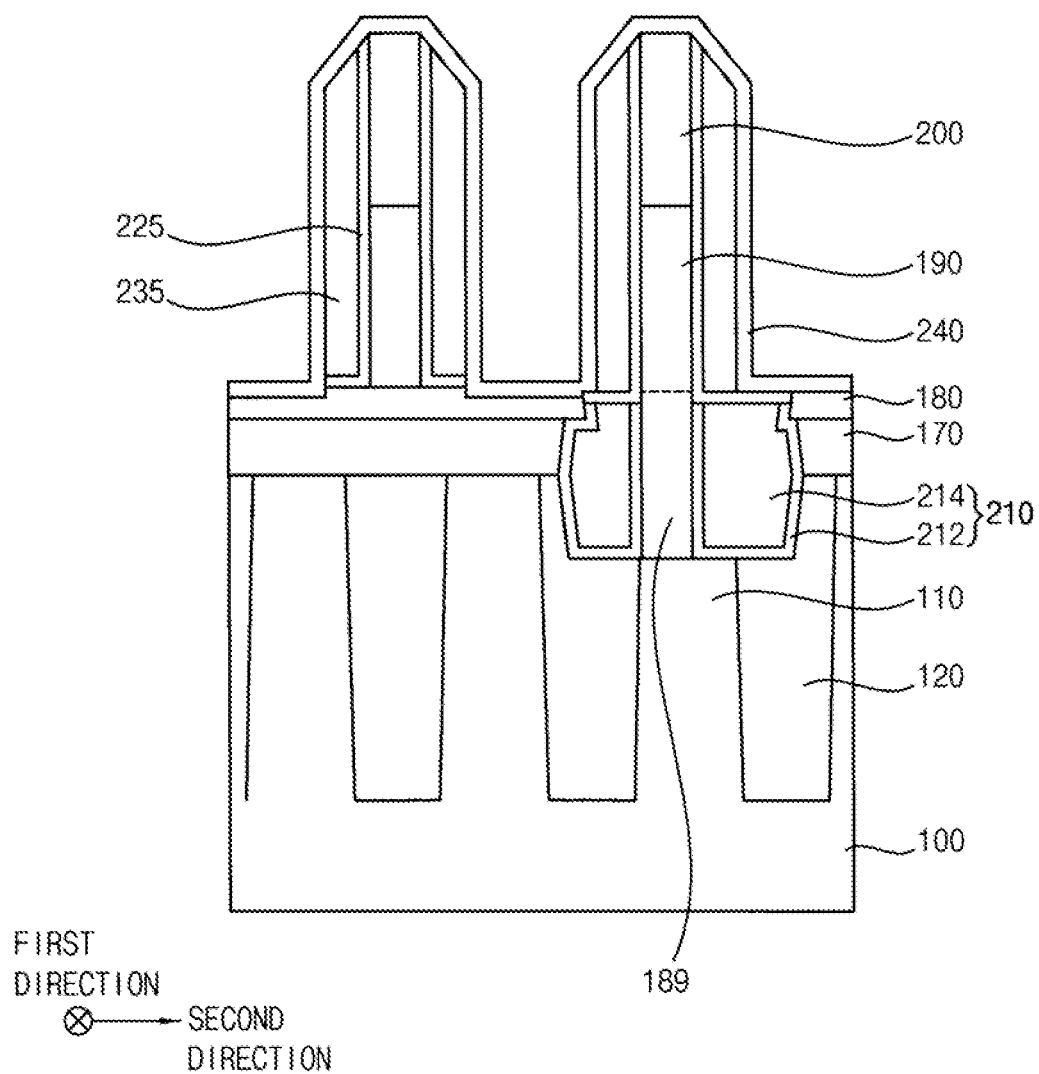


FIG. 18

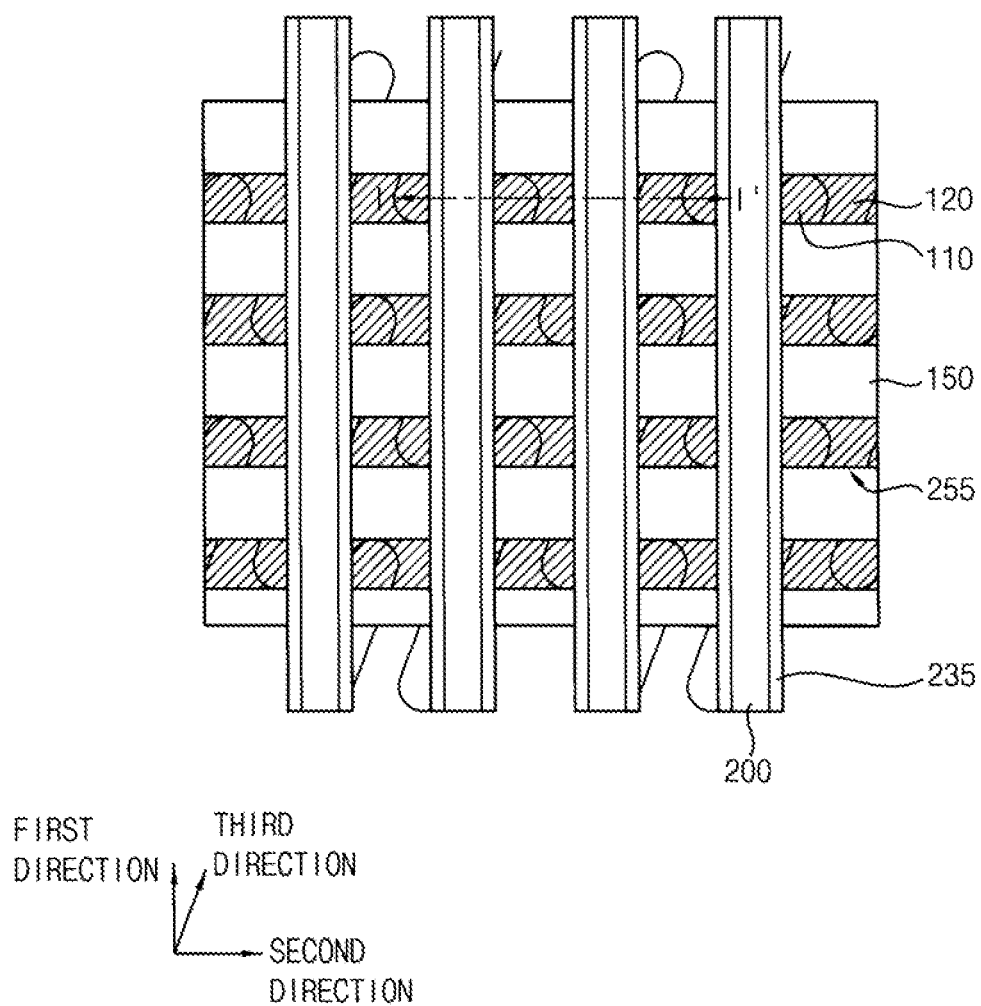


FIG. 19

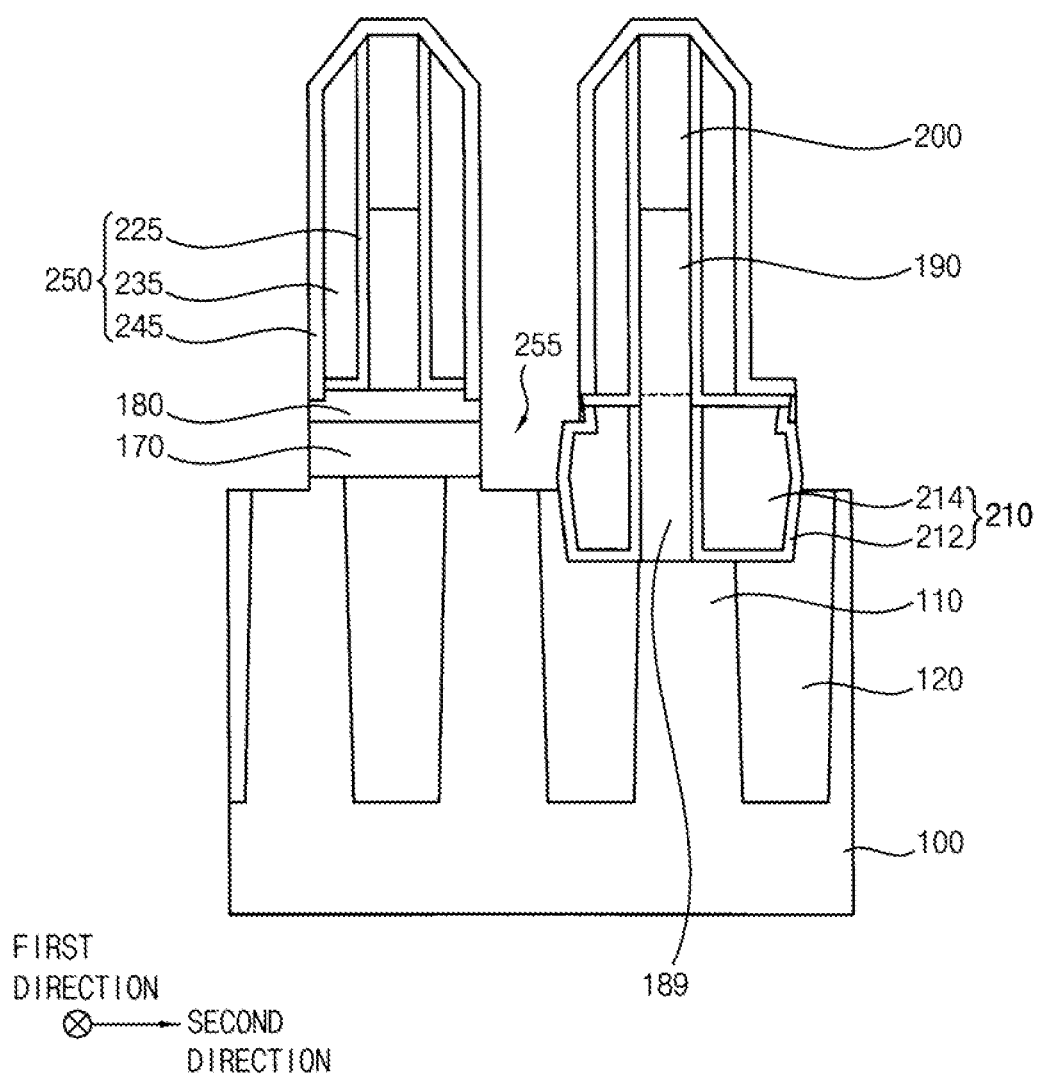


FIG. 20

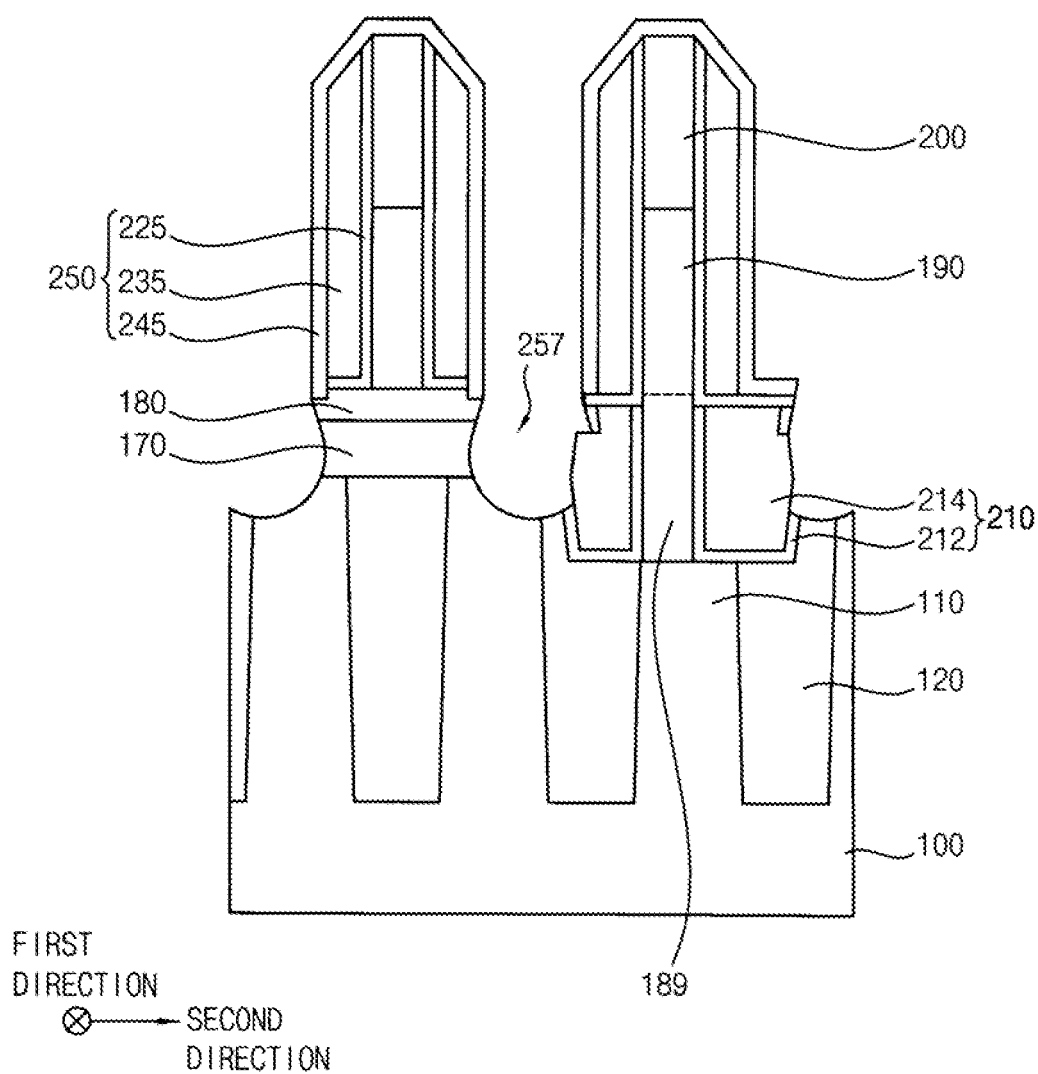


FIG. 21

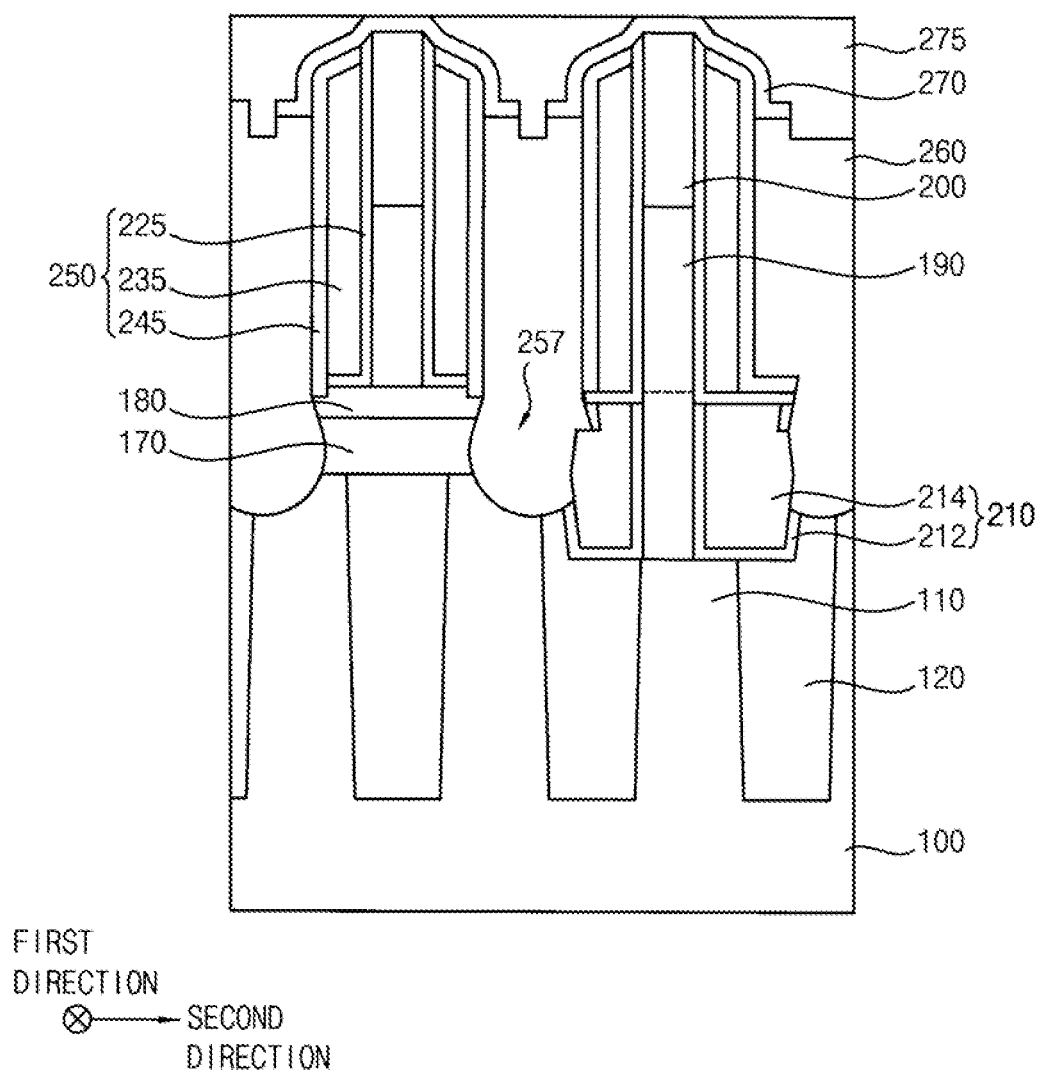


FIG. 22

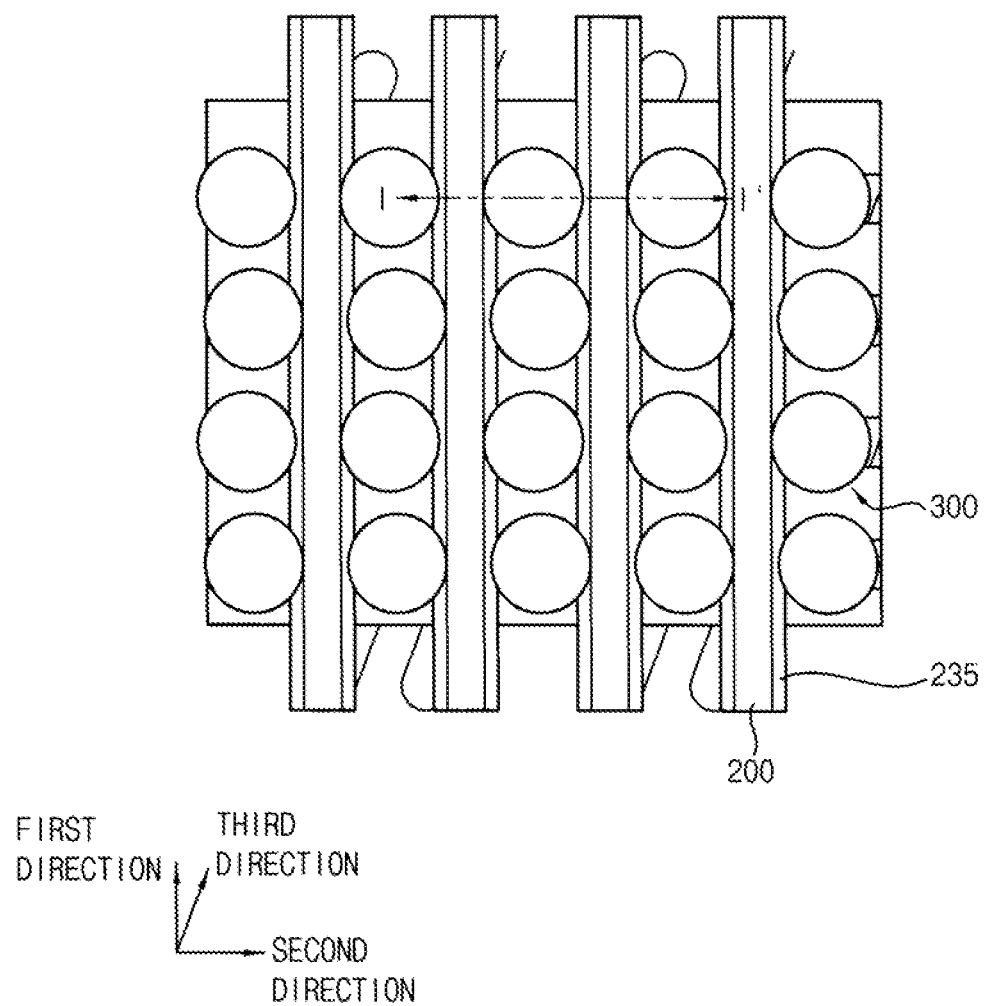
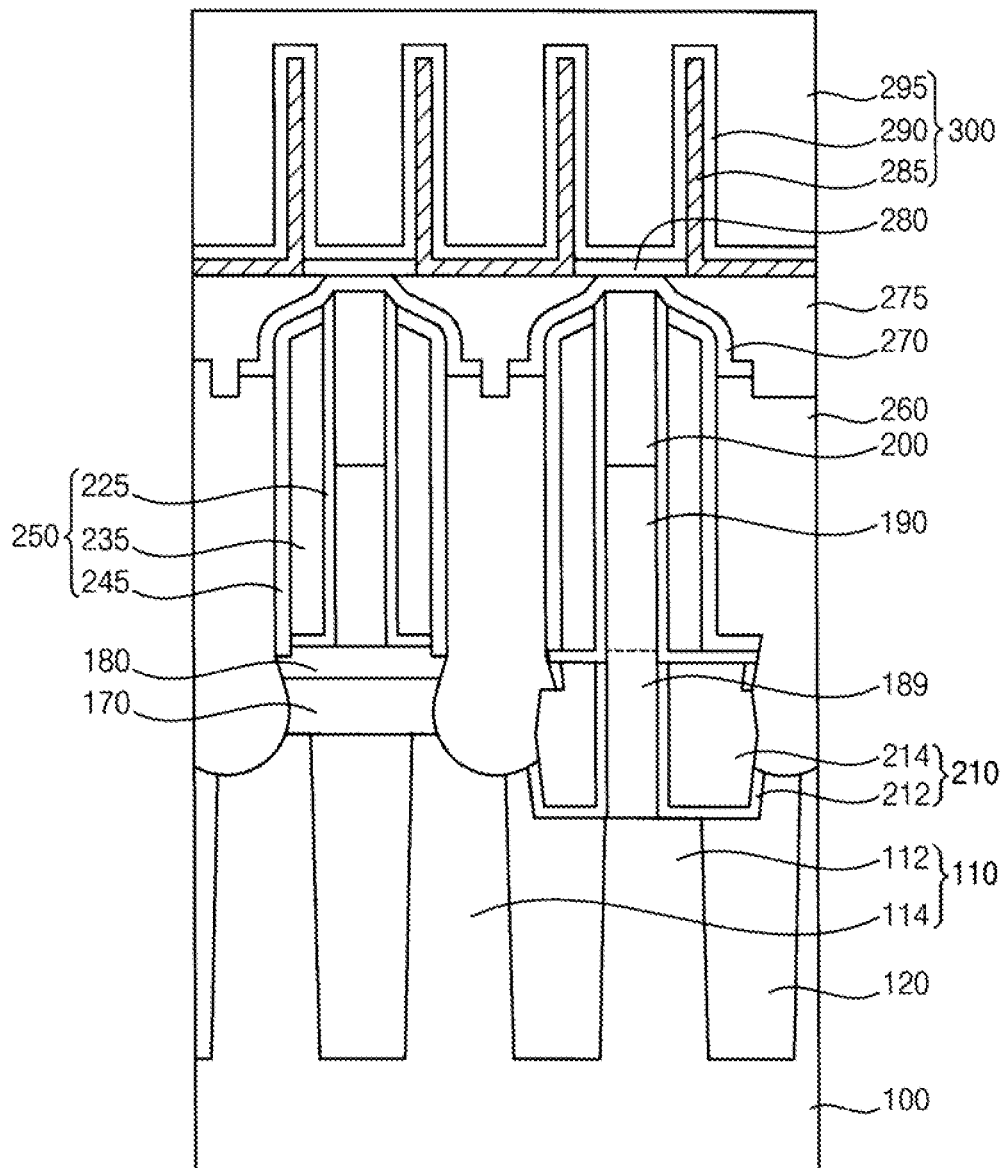


FIG. 23



FIRST  
DIRECTION



- SECOND  
DIRECTION

FIG. 24

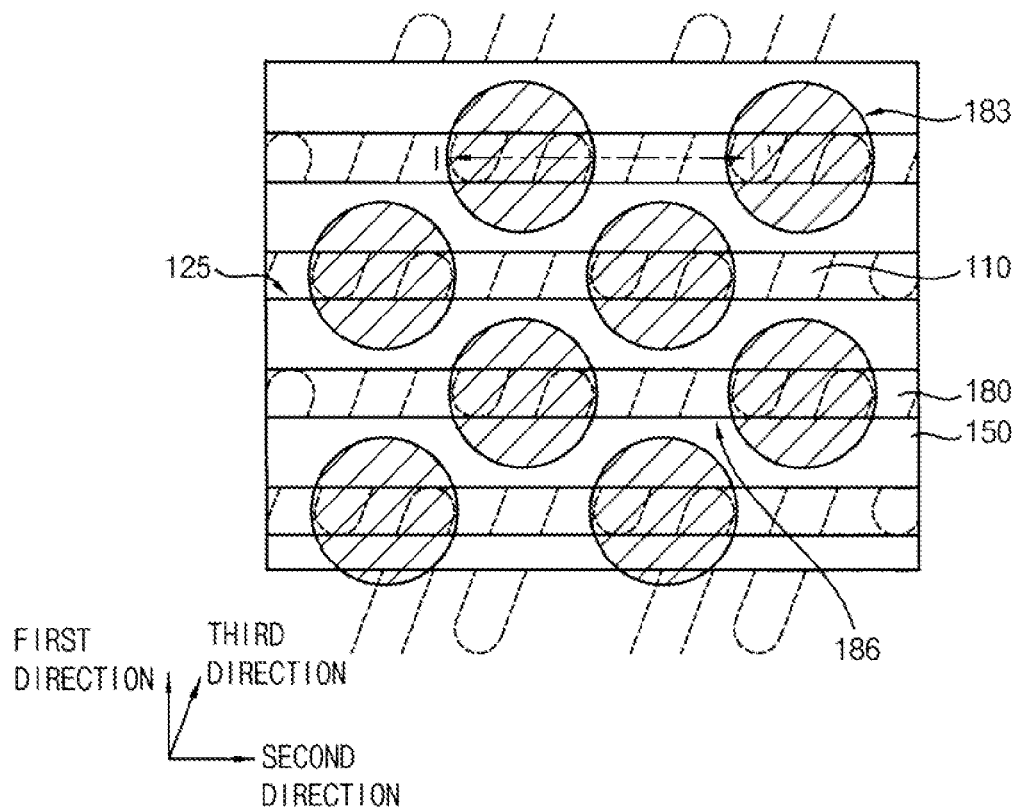


FIG. 25

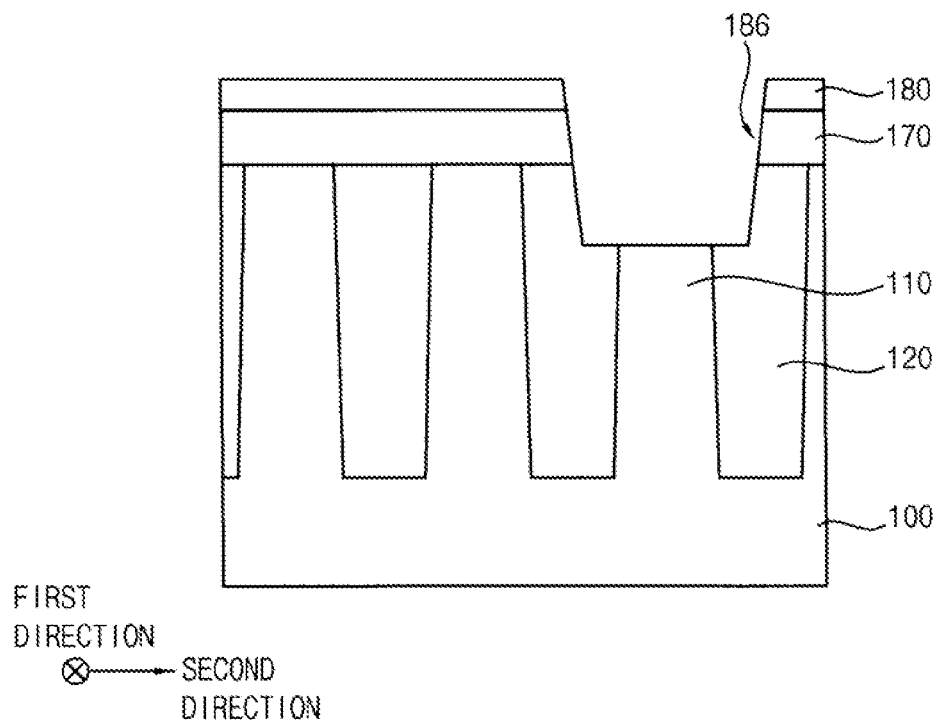




FIG. 26

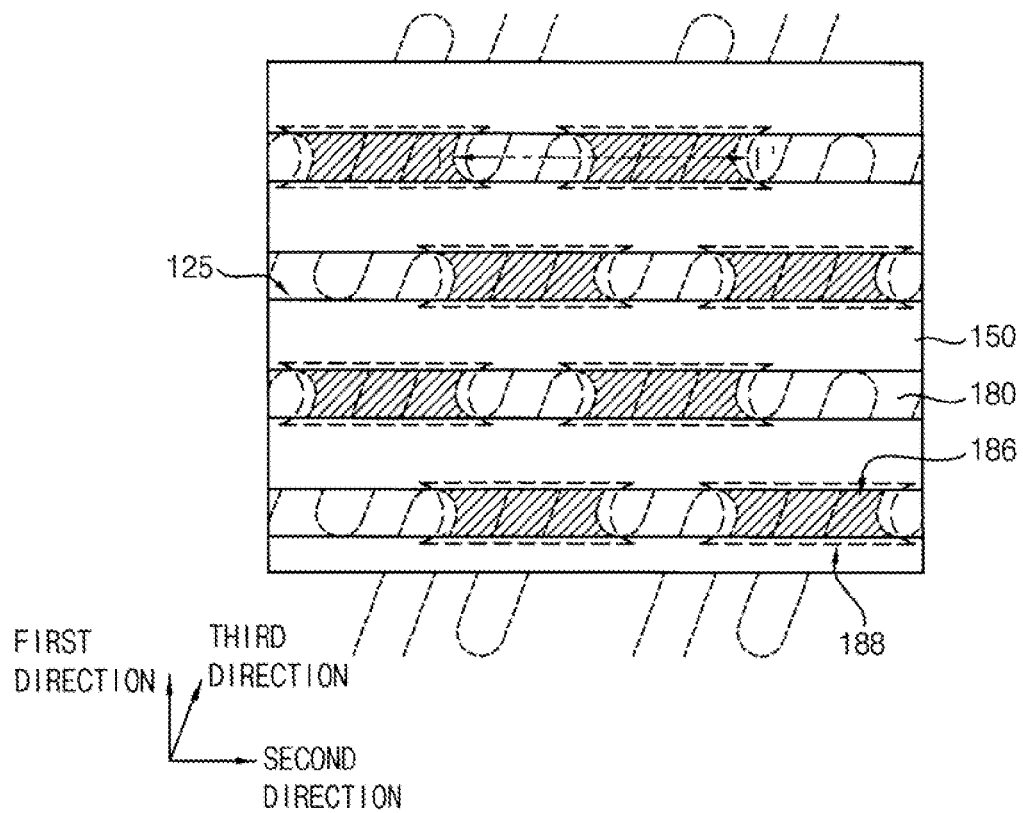


FIG. 27

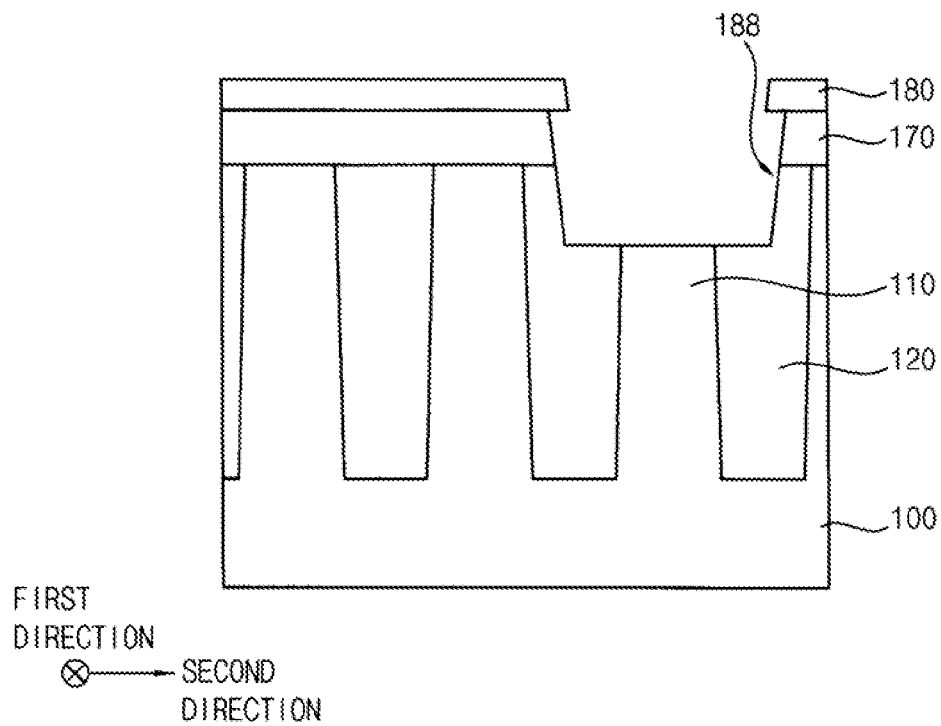


FIG. 28

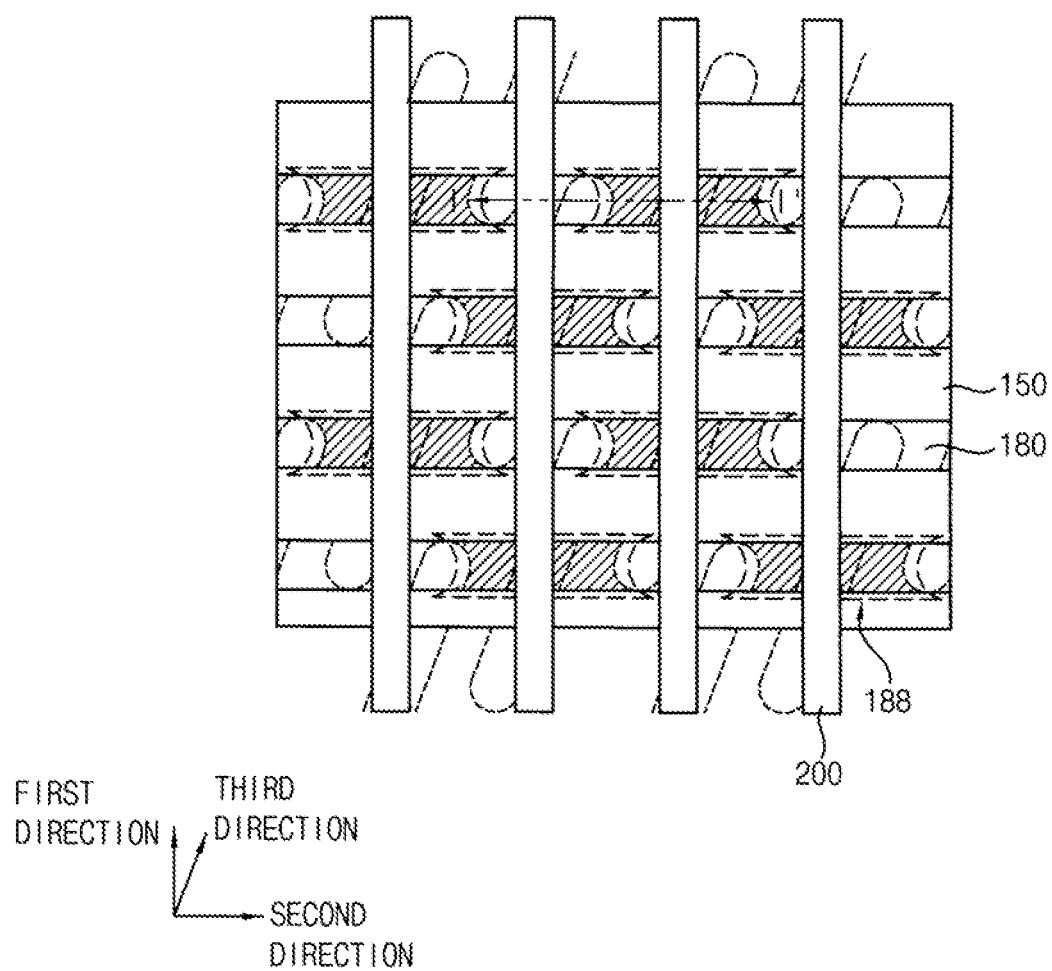


FIG. 29

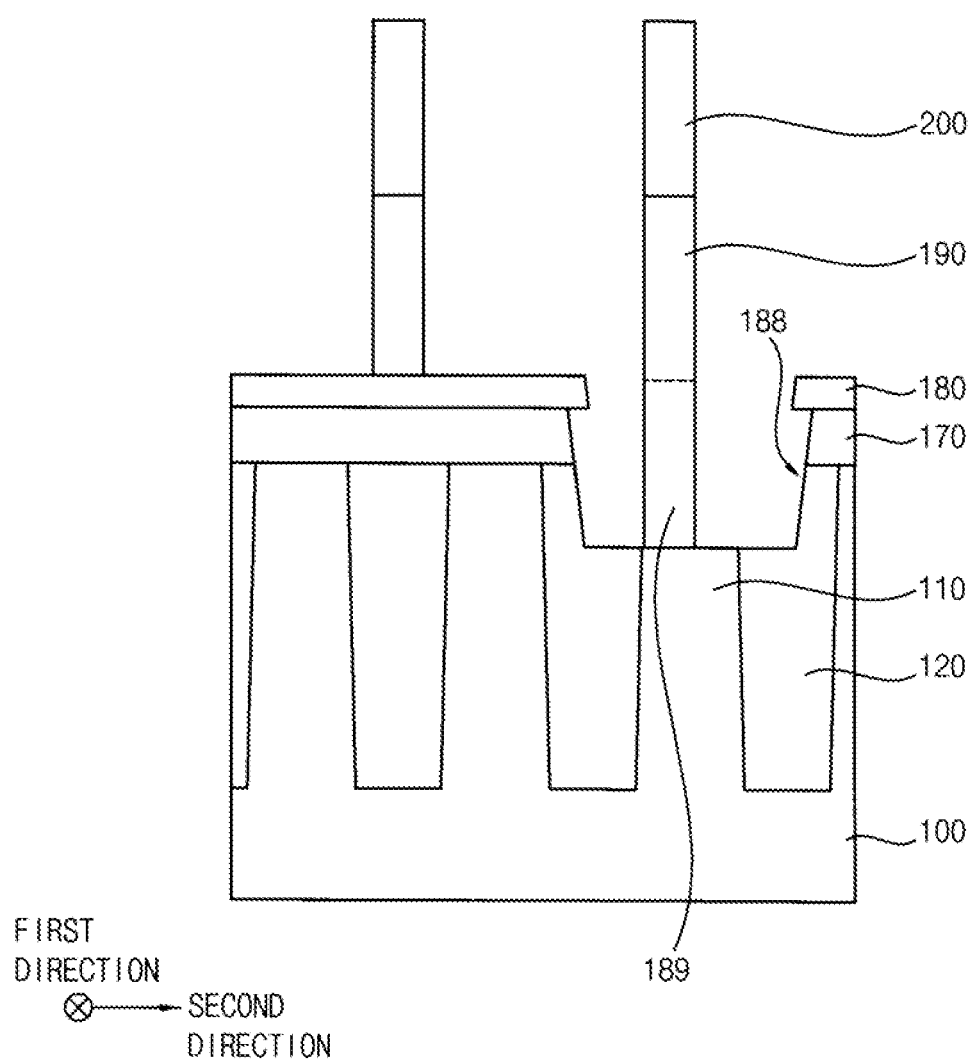
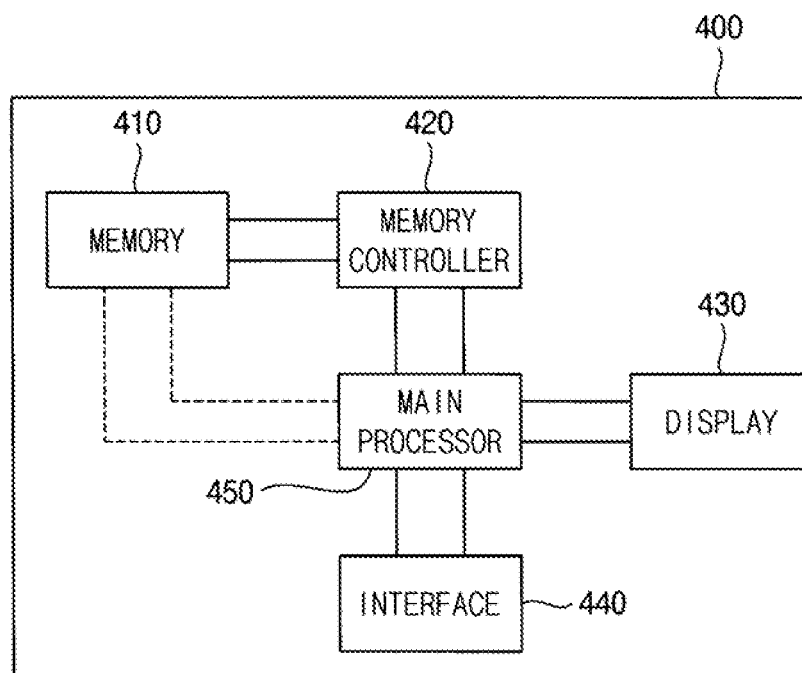


FIG. 30



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# SEMICONDUCTOR DEVICES AND METHODS OF MANUFACTURING THE SAME

## CLAIM OF PRIORITY

This application claims priority under 35 USC §119 from Korean Patent Application No. 10-2013-0151158, filed on Dec. 6, 2013 in the Korean Intellectual Property Office (KIPO), and all the benefits accruing therefrom, the contents of which are herein incorporated by reference in their entirety.

## BACKGROUND

### 1. Technical Field

Exemplary embodiments are directed to semiconductor devices and methods of manufacturing the semiconductor devices.

### 2. Discussion of the Related Art

In a conventional method of manufacturing semiconductor memory devices, spacers may be formed on sidewalls of a bit line and a bit line contact. The spacers may protect and isolate the bit line and the bit line contact. Further, a capacitor contact may be formed between the spacers. Recently, as the degree of integration semiconductor devices increases, a distance between adjacent bit lines decreases. Therefore, a width of spacer disposed on sidewalls of the bit line or a bit line contact may also decrease. However, during processes for manufacturing a semiconductor device, such as an etching process to form a recess to receive the capacitor contact, the spacer may be over-etched or removed, thereby damaging the bit line or the bit line contact.

## SUMMARY

Exemplary embodiments provide a semiconductor device having an improved reliability.

Exemplary embodiments provide a method of manufacturing a semiconductor device having an improved reliability.

According to some exemplary embodiments, there is provided a method of manufacturing a semiconductor device. In the method, an isolation layer is formed on a substrate, in which an active pattern is defined. An insulating interlayer is formed on the active pattern of the substrate and the isolation layer. Portions of the insulating interlayer, the active pattern and the isolation layer are removed to form a first recess. A first contact is formed in the first recess on a first region of the active pattern exposed by the first recess. Portions of the active pattern and the isolation layer are removed by performing an isotropic etching process, to form an enlarged first recess. The enlarged first recess is filled to form a first spacer that surrounds a sidewall of the first contact.

In exemplary embodiments, a bit line may be further formed on the first contact and the insulating interlayer. The bit line may extend parallel to a top surface of the substrate in a first direction. A plurality of second spacers may be formed to surround a sidewall of the bit line.

In exemplary embodiments, forming the enlarged first recess may be performed after forming the first contact and forming the bit line.

In exemplary embodiments, forming the enlarged first recess may be performed before forming the first contact and forming the bit line.

In exemplary embodiments, the first spacer may have a first width in a second direction perpendicular to the first direc-

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tion, the second spacer may have a second width in the second direction, and the first width may greater than or equal to the second width.

In exemplary embodiments, forming the first spacer may include forming a first insulation layer on an inner wall of the enlarged first recess, a sidewall of the first contact, and a top surface of the insulating interlayer, forming a second insulation layer on the first insulation layer, and removing upper portions of the first insulation layer and the second insulation layer.

In exemplary embodiments, the first insulation layer may include silicon oxide, and the second insulation layer may include silicon nitride.

In exemplary embodiments, portions of the insulating interlayer, the active pattern and the isolation layer are removed by an anisotropic etching process to form a second recess between the second spacers, and portions of the insulating interlayer, the active pattern and the isolation layer are removed by an isotropic etching process, to enlarge the second recess. The enlarged second recess may expose a second region of the active pattern.

In exemplary embodiments, an etching solution used by the isotropic etching process has an etch rate with respect to the silicon nitride that may be less than the etch rate with respect to the silicon oxide.

In exemplary embodiments, the enlarged second recess may be filled to form a second contact. A capacitor may be formed to be electrically connected to the second contact.

According to some exemplary embodiments, there is provided a semiconductor device including a substrate, a first contact, a bit line, a first spacer and a second spacer. The substrate includes an active pattern defined by an isolation layer. A first contact is disposed on the active pattern. A bit line disposed on the first contact extends parallel to a top surface of the substrate in a first direction. A first spacer surrounds a sidewall of the first contact. The first spacer has a first width in a second direction perpendicular to the first direction. The second spacer surrounds a sidewall of the bit line. The second spacer has a second width that is less than or equal to the first width.

In exemplary embodiments, the first spacer may include a first insulation layer pattern on the sidewall of the first contact and a top surface of the active pattern, the first insulation layer including silicon oxide, and a second insulation layer pattern on the first insulation layer pattern, the second insulation layer including silicon nitride.

In exemplary embodiments, the second spacer may include a third insulation layer pattern on the sidewall of the bit line and a top surface of the first spacer, a fourth insulation layer pattern on a sidewall of the third insulation layer pattern, and a fifth insulation layer pattern on a sidewall and a top surface of the fourth insulation layer pattern.

In exemplary embodiments, the second spacer may include a third insulation layer pattern on the sidewall of the bit line and a top surface of the first spacer, a fourth insulation layer pattern spaced apart from the third insulation layer pattern in the second direction, a fifth insulation layer pattern on the third insulation layer pattern and the fourth insulation layer pattern, and a void defined by a sidewall and a top surface of the third insulation layer pattern, a sidewall of the fourth insulation layer pattern and a bottom surface of the fifth insulation layer pattern.

According to some exemplary embodiments, there is provided a method of manufacturing a semiconductor device. In the method, portions of an insulating interlayer, an active pattern and an isolation layer on a substrate are removed to form a first recess. A first contact is formed in the first recess

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on a first region of the active pattern exposed by the first recess. A bit line is formed on the first contact and the insulating interlayer. The bit line extends parallel to a top surface of the substrate in a first direction. Portions of the active pattern and the isolation layer in the first recess are removed by performing an isotropic etching process to form an enlarged first recess. The enlarged first recess is filled to form a first spacer that surrounds a sidewall of the first contact. A plurality of second spacers are formed that surround a sidewall of the bit line.

In exemplary embodiments, the isolation layer is formed on a substrate, in which the active pattern is defined, and the insulating interlayer is formed on the active pattern of the substrate and the isolation layer.

In exemplary embodiments, filling the enlarged first recess to form the first spacer may include forming a first insulation layer on an inner wall of the enlarged first recess, a sidewall of the first contact, and a top surface of the insulating interlayer, forming a second insulation layer on the first insulation layer, and removing upper portions of the first insulation layer and the second insulation layer. The method may further include removing portions of the insulating interlayer, the active pattern and the isolation layer by an anisotropic etching process to form a second recess, and removing portions of the insulating interlayer, the active pattern and the isolation layer by an isotropic etching process to enlarge the second recess. An etching solution used by the isotropic etching process may have an etch rate with respect to the second insulation layer that is less than the etch rate with respect to the first insulation layer.

In exemplary embodiments, forming the enlarged first recess may be performed after forming the first contact and forming the bit line.

In exemplary embodiments, forming the enlarged first recess may be performed before forming the first contact and forming the bit line.

In exemplary embodiments, the first spacer may have a first width in a second direction perpendicular to the first direction, the second spacer may have a second width in the second direction, and the first width may be greater than or equal to the second width.

### BRIEF DESCRIPTION OF THE DRAWINGS

FIG. 1 is a plan view of a semiconductor device in accordance with some exemplary embodiments.

FIG. 2 is a cross-sectional view of a semiconductor device in accordance with some exemplary embodiments.

FIG. 3 is a cross-sectional view of a semiconductor device in accordance with some exemplary embodiments.

FIGS. 4 to 23 are plan views and cross-sectional views of stages of a method of manufacturing a semiconductor device in accordance with some exemplary embodiments.

FIGS. 24 to 29 are plan views and cross-sectional views of stages of a method of manufacturing a semiconductor device in accordance with some exemplary embodiments.

FIG. 30 is a block diagram of a system that includes a semiconductor device in accordance with exemplary embodiments.

### DETAILED DESCRIPTION

Various exemplary embodiments will be described more fully hereinafter with reference to the accompanying drawings, in which some exemplary embodiments are shown. Exemplary embodiments may, however, be embodied in many different forms and should not be construed as limited

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to those set forth herein. In the drawings, the sizes and relative sizes of layers and regions may be exaggerated for clarity.

It will be understood that when an element or layer is referred to as being "on," "connected to" or "coupled to" another element or layer, it can be directly on, connected or coupled to the other element or layer or intervening elements or layers may be present. Like numerals may refer to like elements throughout.

Hereinafter, exemplary embodiments will be explained in detail with reference to the accompanying drawings.

FIG. 1 is a plan view of a semiconductor device in accordance with some exemplary embodiments, and FIG. 2 is a cross-sectional view along line I-I' of FIG. 1.

Referring to FIGS. 1 and 2, a semiconductor device may include a substrate 100 that includes an active pattern 110, a gate structure, a bit line 190 and a capacitor 300.

The gate structure may be buried at an upper portion of the substrate 100, and the bit line 190 extending in a first direction, spacers 210 and 250 surrounding the bit line 190 and a hard mask 200 may be disposed on the substrate 100. Further, the capacitor 300 may be disposed above the bit line 190.

The substrate 100 may include a semiconductor, such as silicon, germanium, silicon-germanium, silicon-on-insulator (SOI), or germanium-on-insulator (GOI).

An isolation layer 120 that includes an insulation material such as silicon oxide may be disposed on the substrate 100. In this case, an upper portion of the substrate 100 surrounded by the isolation layer 120 may be defined as the active pattern 110. In exemplary embodiments, a plurality of active patterns 110 may be substantially parallel to a top surface of the substrate 100, spaced apart in the first direction and a second direction substantially perpendicular to the first direction. Each of the active patterns 110 may extend in a third direction obliquely oriented with respect to the first direction.

The gate structure disposed at the upper portion of the substrate 100 may include a gate electrode 140, a gate insulation layer pattern and a capping layer pattern (See FIG. 7). The gate electrode 140 may extend in the second direction. In exemplary embodiments, a plurality of gate electrodes 140 may be spaced apart from each other in the first direction. Further, the gate insulation layer pattern may be disposed between the active pattern 110 and the gate electrode 140, and the capping layer pattern may be disposed on the gate electrode 140.

In exemplary embodiments, at least one of gate structures may be disposed to correspond to single active pattern 110. For example, a single active pattern 110 may correspond to a pair of gate structures which may be spaced apart from each other in the first direction. Therefore, the active pattern 110 may be divided into a first region 112 between the pair of gate structures and second regions 114 disposed at outer portions of the active pattern 110.

A first insulating interlayer 170 and a second insulating interlayer 180 may be sequentially stacked on the active pattern 110, the isolation layer 120 and the gate structure, and under the bit line 190. For example, the first insulating interlayer 170 may include an oxide, such as silicon oxide, and the second insulating interlayer 180 may include a nitride, such as silicon nitride.

The bit line 190 may extend in the first direction. In exemplary embodiments, a plurality of bit lines 190 may be spaced apart in the second direction. For example, the bit line 190 may have a single layered structure or a multi layered structure that includes doped polysilicon and/or a metal, such as tungsten.

A first contact 189 may be disposed through the first and second insulating interlayers 170 and 180. Further, the first

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contact **189** may be disposed between the first region **112** of the active pattern **110** and the bit line **190**. For example, the first contact **189** may include a conductive material, such as doped polysilicon. The first contact **189** may serve as a bit line contact which may electrically connect the bit line **190** with the active pattern **110**.

The hard mask **200** may be disposed on the bit line **190**. For example, the hard mask **200** may include an insulation material, such as silicon nitride.

The first spacer **210** and the second spacer **250** may be disposed on the sidewalls of the bit line **190**, the first contact **189** and the hard mask **200**.

The first spacer **210** may surround the sidewall of the first contact **189**. The first spacer **210** may be wider in a direction parallel to the top surface of the substrate **100**. In exemplary embodiments, the first spacer **210** may have a first width **W1** in the second direction. In particular, the first width **W1** may be a maximum at a central portion of the first spacer **210**. Further, a top surface of the first spacer **210** may be lower than a top surface of the second insulating interlayer **180**.

The first spacer **210** may include a first insulation layer pattern **212** and a second insulation layer pattern **214**. In exemplary embodiments, the first insulation layer pattern **212** may contact the sidewall of first contact **189**, a top surface of the active pattern **110** and a top surface of isolation layer **120**, and the second insulation layer pattern **214** may surround the first insulation layer pattern **212**. For example, the first insulation layer pattern **212** may include an oxide, such as silicon oxide, and the second insulation layer pattern **214** may include a nitride, such as silicon nitride.

The second spacer **250** may be disposed on sidewalls of the bit line **190** and the hard mask **200**. In exemplary embodiments, the second spacer **250** may extend in the first direction along with the bit line **190**. The second spacer **250** may protect and isolate the bit line **190**. The second spacer **250** may have a second width **W2** in the second direction which may be substantially the same as or less than the first width **W1** of the first spacer **210**.

The second spacer **250** may include a third insulation layer pattern **225**, a fourth insulation layer pattern **235** and a fifth insulation layer pattern **245**. The third insulation layer pattern **225**, the fourth insulation layer pattern **235** and the fifth insulation layer pattern **245** may be sequentially disposed on the sidewall of the bit line **190**. For example, the third insulation layer pattern **225** may include a nitride, such as silicon nitride, the fourth insulation layer pattern **235** may include an oxide, such as silicon oxide, and the fifth insulation layer pattern **245** may include a nitride, such as silicon nitride.

The capacitor **300** may be disposed above the hard mask **200**. In exemplary embodiments, a plurality of capacitors **300** may be arranged in the first direction and the second direction, and each of the capacitors **300** may correspond to the second region **114** of the active pattern **100**.

The capacitor **300** may include a lower electrode **285**, a dielectric layer **290** and an upper electrode **295**. In exemplary embodiments, the lower electrode **285** may have a U-shape to increase an area of the dielectric layer **290**. For example, the dielectric layer **290** may include a high k-dielectric material which may have a dielectric constant larger than those of silicon oxide or silicon nitride. The upper electrode **295** may include a metal, a metal nitride or doped polysilicon.

In addition, the lower electrode **285** of the capacitor **300** may pass through an etch stop layer **280** and a sixth insulation layer pattern **270** to be electrically connected to the second region **114** of the active pattern **110** through a second contact **260** and a third contact **275**. That is, the second contact **260** and the third contact **275** may serve as a capacitor contact.

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The second contact **260** is disposed between adjacent second spacers **250** and may directly contact the second region **114** of the active pattern **110**. A lower portion of the second contact **260** may be wider than an upper portion of the second contact **260**. In particular, the lower portion of the second contact **260** may have a bulbous shape. That is, an interface between the lower portion of the second contact **260** and the second region **114** of the active pattern and an interface between the lower portion of the second contact **260** and the first spacer **210** may be curved. Therefore, a contact area between the second contact **260** and the active pattern **110** may increase, so that an electrical resistance between the second contact **260** and the active pattern **110** may decrease.

According to exemplary embodiments, the semiconductor device may include the first contact **189**, the first spacer **210** surrounding the first contact **189**, the bit line **190** and the second spacer **252** surrounding the bit line **190**. Further, the first width **W1** of the first spacer **210** may be substantially the same as or greater than the second width **W2** of the second spacer **250**. That is, the first spacer **210** may be enlarged to more effectively protect the first contact **189** during an etching process that forms a recess for receiving the second contact **260**.

FIG. 3 is a cross-sectional view of a semiconductor device in accordance with some exemplary embodiments. The semiconductor device may be substantially the same as or similar to the semiconductor device described with reference to FIGS. 1 and 2. Thus, like reference numerals refer to like elements, and repetitive explanations thereof will be omitted.

A gate structure may be buried at the upper portion of the substrate **100**. A bit line **190**, spacers **210** and **252** that protect the bit line **190** and a hard mask **200** may be disposed on the substrate **100**. Further, a capacitor **300** may be disposed above the bit line **190**.

An isolation layer **120** that includes silicon oxide or silicon nitride may be disposed on the substrate **100**, and an upper portion of the substrate **100** surrounded by the isolation layer **120** may be defined as the active pattern **110**. Further, the active pattern **110** may be divided into a first region **112** and the second region **114**.

The bit line **190**, which extends in a second direction, may be disposed above the substrate **100**, and the hard mask **200** may be disposed on the bit line **190**. Further, a first contact **189** may be disposed between the bit line **190** and the active pattern **110**.

The first spacer **210** and the second spacer **252** may be disposed on sidewalls of the bit line **190**, the first contact **189** and the hard mask **200**.

The first spacer **210** may surround the sidewall of the first contact **189**. The first spacer **210** may be wider in a direction parallel to the top surface of the substrate **100**. In exemplary embodiments, the first spacer **210** may have a first width **W1** in the second direction. Further, the first spacer **210** may include a first insulation layer pattern **212** and a second insulation layer pattern **214**.

The second spacer **252** may be disposed on sidewalls of the bit line **190** and the hard mask **200**. In exemplary embodiments, the second spacer **252** may extend in the first direction along with the bit line **190**. The second spacer **252** may protect and isolate the bit line **190**. The second spacer **252** may have a second width **W2** in the second direction which may be substantially the same as or less than the first width **W1** of the first spacer **210**.

The second spacer **252** may include a third insulation layer pattern **225**, a fourth insulation layer pattern **245**, a fifth insulation layer pattern **272** and a void **237** defined by the third to fifth insulation layer patterns **225**, **245** and **272**. In

exemplary embodiments, the void **237** may be defined by a sidewall and a top surface of the third insulation layer pattern **225**, a sidewall of the fourth insulation layer pattern **245** and a bottom surface of the fifth insulation layer pattern **272**.

For example, the third insulation layer pattern **225**, the fourth insulation layer pattern **245**, the fifth insulation layer pattern **272** may include a nitride, such as silicon nitride. Further, the void **237** may include air, which has a relatively low dielectric constant, so that the second spacer **252** may reduce a parasitic capacitance between adjacent bit lines **190**.

The capacitor **300** may be disposed above the hard mask **200**. Further, the capacitor **300** may include a lower electrode **285**, a dielectric layer **290** and an upper electrode **295**. In exemplary embodiments, a plurality of capacitors **300** may be arranged in the first direction and the second direction, and each of the capacitors **300** may correspond to the second region **114** of the active pattern **110**.

Accordingly, a semiconductor device may include the first contact **189**, the first spacer **210** surrounding the first contact **189**, the bit line **190** and the second spacer **252** surrounding the bit line **190**. In this case, the enlarged first width W1 of the first spacer **210** may be substantially the same as or greater than the second width W2 of the second spacer **252**. Therefore, the first spacer **210** may effectively protect the first contact **189** during an etching process that forms a recess for receiving the second contact **260**. Further, the second spacer **252** may include the void **237** defined by the third to fifth insulation layer patterns **225**, **245** and **272**. Therefore, the second spacer **252** may reduce a parasitic capacitance between adjacent bit lines **190**.

FIGS. **4** to **23** are plan views and cross-sectional views of stages of a method of manufacturing a semiconductor device in accordance with some exemplary embodiments. FIGS. **4**, **6**, **8A**, **8B**, **10**, **12**, **16**, **18** and **22** are plan views of stages of the method of manufacturing the semiconductor device in accordance with some exemplary embodiments. FIGS. **5**, **9**, **11**, **13**, **14**, **15**, **17**, **19**, **20**, **21** and **23** are cross-sectional views along lines I-I' of the plan views, and FIG. **7** is cross-sectional views along line II-II' of FIG. **6**.

Referring to FIGS. **4** and **5**, an isolation layer **120** may be formed on a substrate **100**, which defines an active pattern **110**.

The substrate **100** may include a semiconductor, such as silicon, germanium, silicon-germanium, a silicon-on-insulator (SOI), or a germanium-on-insulator (GOI).

The isolation layer **120** may be formed by a shallow trench isolation (STI) process using silicon oxide and/or silicon nitride. That is, an upper portion of the substrate **100** may be removed to form a first trench **105**, and the isolation layer **120** may be formed to fill the first trench **105**. Therefore, the substrate **100** may be divided into a field region where the isolation layer **120** may be disposed and an active region where no isolation layer **120** may be disposed, and an upper portion of the substrate **100** in the active region may be defined as the active pattern **110**.

In exemplary embodiments, a plurality of active patterns **110** may be substantially parallel to a top surface of the substrate **100**, spaced apart in a first direction and a second direction substantially perpendicular to the first direction. Each of the active patterns **110** may extend in a third direction obliquely oriented with respect to the first direction.

Further, impurities such as n-type impurities or p-type impurities may be doped into the substrate **100** before forming the isolation layer **120**.

Referring to FIGS. **6** and **7**, upper portions of the substrate **100** and the isolation layer **120** may be removed to form a

second trench **125**. Then, a gate insulation layer pattern **130**, a gate electrode **140**, and a gate mask **150** may be formed to fill the second trench **125**.

The second trench **125** may extend in the second direction. In exemplary embodiments, a plurality of second trenches **125** may be spaced apart from each other in the first direction. For example, a pair of second trenches **125** may be disposed to overlap a single active pattern **110** as illustrated in FIG. **6**. Therefore, the active pattern **110** may be divided into a first region **112** between the pair of second trenches **125** and second regions **114** at outer portions of the active pattern **110**.

The gate insulation layer pattern **130** and the gate electrode **140** may be formed by filling the second trench **125** on the substrate **100** and the isolation layer **120** with a gate insulation layer and a gate electrode layer, and by planarizing upper portions of the gate insulation layer and the gate electrode layer by an etch back process or a CMP process. The gate electrode **140** may extend in the second direction, and may serve as a word line of the semiconductor device.

In exemplary embodiment, the gate insulation layer may be formed by thermally oxidizing a surface of the substrate **100** exposed by the second trench **125**, or by performing a chemical vapor deposition (CVD) process or an atomic layer deposition (ALD) process using silicon oxide or a metal oxide. Further, the gate electrode layer may be formed using a metal or a metal nitride, such as tungsten (W), tantalum nitride (Ta<sub>2</sub>N<sub>3</sub>), titanium nitride (TiN), and/or tungsten nitride (WN), by a physical vapor deposition process, an ALD process, or a sputtering process.

Then, the gate mask **150** may be formed on the gate electrode **140** to fill an upper portion of the second trench **125**. For example, the gate mask layer may be formed using silicon nitride or silicon oxy-nitride.

Therefore, a gate structure **160** may be formed that includes the gate insulation layer pattern **130**, the gate electrode **140**, and the gate mask **150**. For example, the gate electrode **140** of the gate structure may be buried at the upper portion of the substrate **100**, so that the gate structure may constitute a buried channel array transistor.

Referring to FIGS. **8A** and **9**, a first insulating interlayer **170** and a second insulating interlayer **180** may be formed on the substrate **100**, the isolation layer **120** and the gate structure **160**, and then a first recess **185** that exposes the first region **112** of the active pattern **110** may be formed.

For example, the first insulating interlayer **170** may include an oxide, such as silicon oxide, and the second insulating interlayer **180** may include a nitride, such as silicon nitride. Therefore, the first insulating interlayer **170** and the second insulating interlayer **180** may have an etch selectivity with respect to each other.

Then, portions of the first insulating interlayer **170**, the second insulating interlayer **180**, the active pattern **110** and the isolation layer **120** may be removed to form the first recess **185**. That is, the first recess **185** may be defined by a top surface of the active pattern **110**, a top surface and a sidewall of the isolation layer **120**, a sidewall of the first insulating interlayer **170** and a sidewall of the second insulating interlayer **180**. Therefore, a bottom surface of the first recess **185** may be substantially lower than a top surface of the active pattern **110**.

The first recess **185** may expose the first region **112** of the active pattern **110**. In exemplary embodiment, a mask may be formed on the second insulating interlayer **180**, and then an etching process may be performed using the mask as an etching mask to expose the first region **112** of the active pattern **110**, to form the first recess **185**.



In other exemplary embodiments, a mask **183** covering the second region **114** of the active pattern **110** may be formed on the second insulating interlayer **180** as illustrated in FIG. **8B**, and then an etching process may be performed using the mask **183** as an etching mask, to form the first recess **185**.

Referring to FIGS. **10** and **11**, a first contact **189**, a bit line **190** and a hard mask **200** may be formed on the substrate **100** in the first recess **185** and on the second insulating interlayer **180**.

In particular, a first conductive layer, a second conductive layer and a hard mask layer may be sequentially formed on the substrate **100** and the second insulating interlayer **180** to fill the first recess **185**, and then the first conductive layer, the second conductive layer and the hard mask layer may be partially removed to form the first contact **189**, the bit line **190** and the hard mask **200**.

The first contact **189** and the bit line **190** may be formed using a metal, a metal nitride or doped polysilicon. For example, the first contact **189** may include doped polysilicon, and the bit line **190** may have a multi layered structure that includes doped polysilicon and a metal, such as tungsten. Further, the hard mask **200** may include a nitride, such as silicon nitride.

The bit line **190** and the hard mask **200** may extend in the first direction. In exemplary embodiments, a plurality of bit lines **190** and a plurality of hard masks **200** may be spaced apart in the second direction. Further, the first contact **189** may be disposed in the first recess **185**, to directly contact the first region **112** of the active pattern **110**. Therefore, the first contact **189** may electrically connect the bit line **190** with the first region **112** of the active pattern **110**. That is, the first contact **189** may serve as a bit line contact.

Referring to FIGS. **12** and **13**, portions of the active pattern **110**, the isolation layer **120** and the first insulating interlayer **170** exposed by the first recess **185** may be removed to form an enlarged first recess **187**.

In exemplary embodiments, a wet etching process may be performed to expand the first recess **185**. For example, the wet etching process may use an etching solution and may be an isotropic etching process. In this case, the etching solution may have a relatively low etch rate with respect to the second insulating interlayer **180**, to remove portions of the active pattern **110**, the isolation layer **120** and the first insulating interlayer **170** not covered by the second insulating interlayer **180**.

Therefore, the enlarged first recess **187** may be defined by the top surface of active pattern **110**, the top surface and the sidewall of the isolation layer **120**, the sidewall of the first insulating interlayer **170** and the sidewall and a bottom surface of the second insulating interlayer **180**. In this case, a portion of the enlarged first recess **187** defined by the first insulating interlayer **170** may be substantially wider than a portion of the enlarged first recess **187** defined by the second insulating interlayer **180**.

Referring to FIG. **14**, a first spacer **210** may be formed to fill the enlarged first recess **187**.

In particular, a first insulation layer and a second insulation layer may be sequentially formed on an inner wall of the enlarged first recess **187**, a sidewall of the bit line **190**, a top surface and the sidewall of the hard mask **200** and the top surface of the second insulating interlayer **180**, and then upper portions of the first and second insulation layers may be removed to form the first insulation layer pattern **212** and the second insulation layer pattern **214** that fill the enlarged first recess **187**.

Therefore, the first spacer **210** may be formed that includes the first insulation layer pattern **212** and the second insulation

layer pattern **214**. The first spacer **210** may surround the sidewall of the first contact **189** and fill the enlarged first recess **187**. Therefore, the first spacer **210** may have a shape that corresponds to the enlarged first recess **187**. That is, the first spacer **210** may be wider in a direction parallel to the top surface of the substrate **100**. In exemplary embodiments, a first width **W1** of the first spacer **210** may be substantially greater than or equal to a second width **W2** of the second spacer **250** (See FIG. **17**). Further, a top surface of the first spacer **210** may be lower than the top surface of the second insulating interlayer **180**.

For example, the first insulation layer pattern **212** may include an oxide, such as silicon oxide, and the second insulation layer pattern **214** may include a nitride, such as silicon nitride.

Referring to FIG. **15**, a third insulation layer **220** and a fourth insulation layer **230** may be formed on a top surface of the second insulating interlayer **180**, the sidewall of the bit line **190**, the top surface and the sidewall of the hard mask **200** and a top surface of the first spacer **210**.

In exemplary embodiments, the third insulation layer **220** may include a nitride, such as silicon nitride, and the fourth insulation layer **230** may include an oxide, such as silicon oxide.

Referring to FIGS. **16** and **17**, the third insulation layer **220** and the fourth insulation layer **230** may be partially removed to form the third insulation layer pattern **225** and the fourth insulation layer pattern **235**. Then, a fifth insulation layer **240** may be formed to cover the third insulation layer pattern **225** and the fourth insulation layer pattern **235**.

In particular, an anisotropic etching process may be performed to partially remove the third insulation layer **220** and the fourth insulation layer **230**. Therefore, the third insulation layer pattern **225** may be disposed on the sidewall of the bit line **190**, the sidewall of the hard mask **200** and the top surface of the first spacer **210**, and the fourth insulation layer pattern **235** may be disposed on the third insulation layer pattern **225**. The third insulation layer pattern **225** and the fourth insulation layer pattern **235** may extend in the first direction. In exemplary embodiments, a plurality of third insulation layer patterns **225** and a plurality of fourth insulation layer patterns **235** may be spaced apart in the second direction.

Further, the fifth insulation layer **240** may be formed to cover the third insulation layer pattern **225**, the fourth insulation layer pattern **235** and the hard mask **200**. In exemplary embodiments, the fifth insulation layer **240** may include a nitride, such as silicon nitride.

Referring to FIGS. **18** and **19**, portions of the fifth insulation layer **240**, the second insulating interlayer **180**, the first insulating interlayer **170**, the isolation layer **120** and the active pattern **110** between the second spacers may be removed to form a second recess **255**.

In exemplary embodiments, an etching process that uses the fourth insulation layer pattern **235**, the hard mask **220** and the gate mask **150** as an etching mask may be performed to remove portions of the fifth insulation layer **240**, the second insulating interlayer **180**, the first insulating interlayer **170**, the isolation layer **120** and the active pattern **110**. The etching process may be an anisotropic etching process, and the second recess **255** may partially expose the active pattern **110** and the isolation layer **120**.

In other exemplary embodiments, before performing the etching process, an insulation layer pattern that overlaps the gate mask **150** may be formed on the fifth insulation layer **240**, and the insulation layer pattern may be used as an etching mask.

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Therefore, the second recess **255** may be defined by a top surface of the second region **114** of the active pattern **110**, the top surface of the isolation layer **120**, the sidewall of the first insulating interlayer **170**, the sidewall of the second insulating interlayer **180** and the sidewall of the first insulation layer pattern **212** (or the second insulation layer pattern **214**).

Further, portions of fifth insulation layer **240** may be removed during the etching process, to form a fifth insulation layer pattern **245**. Therefore, a second spacer **250** may be formed that includes the third insulation layer pattern **225**, the fourth insulation layer pattern **235** and the fifth insulation layer pattern **245**. The second spacer **250** may surround the sidewalls of the bit line **190** and the hard mask **200**. The second spacer **250** may have a second width in the second direction which may be substantially equal to or less than the first width of the first spacer **210**.

Referring to FIG. **20**, portions of the second insulating interlayer **180**, the first insulating interlayer **170**, the isolation layer **120** and the active pattern **110** may be removed to form an enlarged second recess **257**.

In particular, a wet etching process that uses an etching solution may be performed to expand the second recess **255**. In this case, the etching solution may have a relatively low etch rate with respect to the second insulation layer pattern **214**, and a relatively high etch rate with respect to the first insulation layer pattern **212**.

Therefore, the enlarged second recess **257** may be defined by the top surface of the active pattern **110**, the top surface of the isolation layer **120**, the sidewall of the first insulating interlayer **170**, the sidewall of the second insulating interlayer **180** and the sidewall of the second insulation layer pattern **214**. As the second recess **255** may be enlarged, an area of the active pattern **110** exposed by the enlarged second recess **257** may increase.

Further, the first width of the first spacer **210** may be greater than the second width of the second spacer **250**, so that the first contact **189** may not be exposed by the enlarged second recess **257**, even though the first spacer **210** is partially removed or damaged during the etching process. Therefore, the first spacer **210** may effectively protect the first contact **189**, and the semiconductor device may have an improved reliability.

Referring to FIG. **21**, a second contact **260**, a sixth insulation layer pattern **270** and a third contact **275** may be formed.

A third conductive layer may be formed on the hard mask **200** and the fifth insulation layer pattern **245** to fill the enlarged second recess **257**, and then an upper portion of the third conductive layer may be removed to form the second contact **260**.

Therefore, the second contact **260** may directly contact the top surface of the second region **114** of the active pattern **110**. A direct contact area between the second contact **260** and the active pattern **110** may increase, which may decrease an electrical resistance between the second contact **260** and the active pattern **110**.

Then, a sixth insulation layer may be formed on the hard mask **200**, the fifth insulation layer pattern **245** and the second contact **260**, and then portions of the sixth insulation layer may be removed to form the sixth insulation layer pattern **270**.

In addition, the third contact **275** may be disposed on the sixth insulation layer pattern **270**, and may be electrically connected to the second contact **260**. That is, the third contact **275** may be electrically connected to the second region **114** of the active pattern **110** by the second contact **260**. That is, the second contact **260** and the third contact **275** may serve as a capacitor contact.

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Referring to FIGS. **22** and **23**, a capacitor **300** may be formed to be electrically connected to the third contact **275**.

The capacitor **300** may include a lower electrode **285**, a dielectric layer **290** and an upper electrode **295**.

To forming the lower electrode **285**, an etch stop layer **280** and a third insulating interlayer may be formed on the third contact **275**, and portions of the etch stop layer **280** and the third insulating interlayer may be removed to form an opening exposing the third contact **275**. A lower electrode layer may be formed on an inner wall of the opening, and an upper portion of the lower electrode layer may be planarized, thereby forming the lower electrode **285**. Then, the third insulating interlayer may be removed.

The dielectric layer **290** may be formed using a high dielectric material that has a dielectric constant substantially greater than that of silicon oxide or silicon nitride. For example, the high dielectric material may include at least one of tantalum oxide, hafnium oxide, aluminum oxide, zirconium oxide, etc. The high dielectric material may be used alone, or as a mixture thereof. The dielectric layer **290** may be formed by a CVD process, a PVD process, an ALD process, etc.

Then, the upper electrode **295** may be formed using a metal, a metal nitride or doped polysilicon by a CVD process, a PVD process, an ALD process, etc. The upper electrode **295** may be a cylinder type or a thin film type. Therefore, the capacitor **300** may be formed that includes the lower electrode **285**, the dielectric layer **290** and the upper electrode **295**.

By performing the above processes, a semiconductor device may be completed.

FIGS. **24** to **29** are plan views and cross-sectional views of stages of a method of manufacturing a semiconductor device in accordance with other exemplary embodiments. Some aspects of the methods illustrated in FIGS. **24** to **29** are substantially the same as or similar to those illustrated with reference to FIGS. **4** to **23**. Thus, like reference numerals may refer to like elements, and repetitive explanations thereof will be omitted.

Referring to FIGS. **24** and **25**, processes substantially the same as or similar to those described with reference to FIGS. **4** to **9** may be performed. That is, an isolation layer **120** may be formed on a substrate **100**, to define an active pattern **110**. Upper portions of the substrate **100** and the isolation layer **120** may be removed to form a second trench **125**, and then gate structure that includes a gate insulation layer pattern **130**, a gate electrode **140**, and a gate mask **150** may be formed to fill the second trench **125**. A first insulating interlayer **170** and a second insulating interlayer **180** may be formed on the substrate **100**, the isolation layer **120** and the gate structure, and then a first recess **186** exposing a first region **112** of the active pattern **110** may be formed.

Referring to FIGS. **26** and **27**, portions of the active pattern **110**, the isolation layer **120** and the first insulating interlayer **170** exposed by the first recess **186** may be removed to form an enlarged first recess **188**. The etching process may be substantially the same as those described with reference to FIGS. **12** and **13**.

Referring to FIGS. **28** and **29**, a first contact **189**, a bit line **190** and a hard mask **200** may be formed on the substrate **100** in the enlarged first recess **188** and on the second insulating interlayer **180**. The process may be substantially the same as those described with reference to FIGS. **10** and **11**.

Then, by performing processes substantially the same as those described with reference to FIGS. **14** and **23**, a semiconductor device may be completed.

## 13

FIG. 30 is a block diagram of a system that includes a semiconductor device in accordance with exemplary embodiments.

Referring to FIG. 30, a system 400 may include a memory 410, a memory controller 420 that controls the operation of the memory 410, a displaying part 430 that outputs information, an interface 440 that receives information, and a main processor 450 that controls the above described parts. The memory 410 may be a semiconductor device in accordance with exemplary embodiments. The memory 410 may be directly connected to the main processor 450 or through a bus. The system 400 may be used with, e.g., a computer, a portable computer, a laptop computer, a personal portable terminal, a tablet, a cellular phone, a digital music player, etc.

Exemplary embodiments have been disclosed herein, and although specific terms are employed, they are used and are to be interpreted in a generic and descriptive sense only and not for purpose of limitation. In some instances, as would be apparent to one of ordinary skill in the art as of the filing of the present application, features, characteristics, and/or elements described in connection with a particular embodiment may be used singly or in combination with features, characteristics, and/or elements described in connection with other embodiments unless otherwise specifically indicated. Accordingly, it will be understood by those of skill in the art that various changes in form and details may be made without departing from the spirit and scope of the present invention as set forth in the following claims.

What is claimed is:

1. A method of manufacturing a semiconductor device, comprising:

forming an isolation layer on a substrate, wherein an active pattern is defined, the active pattern including a material substantially the same as that of the substrate;

forming an insulating interlayer on the active pattern of the substrate and the isolation layer;

removing portions of the insulating interlayer, the active pattern and the isolation layer to form a first recess;

forming a first contact in the first recess on a first region of the active pattern exposed by the first recess;

removing portions of the active pattern and the isolation layer exposed by the first recess by performing an isotropic etching process, to form an enlarged first recess; and

filling the enlarged first recess to form a first spacer that surrounds a sidewall of the first contact.

2. The method as claimed in claim 1, further comprising: forming a bit line on the first contact and the insulating interlayer, wherein the bit line extends parallel to a top surface of the substrate in a first direction; and forming a plurality of second spacers that surround a sidewall of the bit line.

3. The method as claimed in claim 2, wherein forming the enlarged first recess is performed after forming the first contact and forming the bit line.

4. The method as claimed in claim 2, wherein forming the enlarged first recess is performed before forming the first contact and forming the bit line.

5. The method as claimed in claim 2, wherein the first spacer has a first width in a second direction perpendicular to the first direction, the second spacer has a second width in the second direction, wherein the first width is greater than or equal to the second width.

6. The method as claimed in claim 2, wherein filling the enlarged first recess to form the first spacer includes:

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forming a first insulation layer on an inner wall of the enlarged first recess, a sidewall of the first contact, and a top surface of the insulating interlayer;

forming a second insulation layer on the first insulation layer; and

removing upper portions of the first insulation layer and the second insulation layer.

7. The method as claimed in claim 6, wherein the first insulation layer includes silicon oxide, and the second insulation layer includes silicon nitride.

8. The method as claimed in claim 7, further comprising: removing portions of the insulating interlayer, the active pattern and the isolation layer by an anisotropic etching process to form a second recess between the second spacers, wherein the second recess exposes a second region of the active pattern, and

removing portions of the insulating interlayer, the active pattern and the isolation layer by an isotropic etching process to enlarge the second recess.

9. The method as claimed in claim 8, wherein an etching solution used by the isotropic etching process has an etch rate with respect to the silicon nitride that is less than the etch rate with respect to the silicon oxide.

10. The method as claimed in claim 8, further comprising: filling the enlarged second recess with a second contact; and

forming a capacitor electrically connected to the second contact.

11. A method of manufacturing a semiconductor device, comprising:

removing portions of an insulating interlayer, an active pattern and an isolation layer on a substrate to form a first recess, the active pattern including a material substantially the same as that of the substrate;

forming a first contact in the first recess on a first region of the active pattern exposed by the first recess;

forming a bit line on the first contact and the insulating interlayer, wherein the bit line extends parallel to a top surface of the substrate in a first direction;

removing portions of the active pattern and the isolation layer in the first recess by performing an isotropic etching process, to form an enlarged first recess;

filling the enlarged first recess to form a first spacer that surrounds a sidewall of the first contact; and

forming a plurality of second spacers that surround a sidewall of the bit line.

12. The method as claimed in claim 11, further comprising forming the isolation layer is on a substrate, wherein the active pattern is defined; and forming the insulating interlayer on the active pattern of the substrate and the isolation layer.

13. The method as claimed in claim 11, wherein filling the enlarged first recess to form the first spacer includes:

forming a first insulation layer on an inner wall of the enlarged first recess, a sidewall of the first contact, and a top surface of the insulating interlayer;

forming a second insulation layer on the first insulation layer; and

removing upper portions of the first insulation layer and the second insulation layer, and further comprising:

removing portions of the insulating interlayer, the active pattern and the isolation layer by an anisotropic etching process to form a second recess; and

removing portions of the insulating interlayer, the active pattern and the isolation layer by an isotropic etching process to enlarge the second recess,

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wherein an etching solution used by the isotropic etching process has an etch rate with respect to the second insulation layer that is less than the etch rate with respect to the first insulation layer.

**14.** The method as claimed in claim **11**, wherein forming the enlarged first recess is performed after forming the first contact and forming the bit line. 5

**15.** The method as claimed in claim **11**, wherein forming the enlarged first recess is performed before forming the first contact and forming the bit line. 10

**16.** The method as claimed in claim **11**, wherein the first spacer has a first width in a second direction perpendicular to the first direction, the second spacer has a second width in the second direction, wherein the first width is greater than or equal to the second width. 15

\* \* \* \* \*

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